±0.5°C Accurate Digital Temperature Sensor and Quad Voltage Output 12-/10-/8-Bit DACs

ADT7316/ADT7317/ADT7318

FEATURES

ADT7316—four 12-bit DACs
ADT7317—four 10-bit DACs
ADT7318—four 8-bit DACs
Buffered voltage output
Guaranteed monotonic by design over all codes
10-bit temperature-to-digital converter
Temperature range: –40°C to +120°C
Temperature sensor accuracy of ±0.5°C
Supply range: 2.7 V to 5.5 V
DAC output range: 0 V to 2 V_{REF}
Power-down current : <10 µA
Internal 2.28 V_{REF} option
Double-buffered input logic
Buffered/unbuffered reference input option
Power-on reset to 0 V
Simultaneous update of outputs ($\overline{LDAC}$ function)
On-chip rail-to-rail output buffer amplifier
I²C®-, SMBus-, SPI®-, QSPI™-, MICROWIRE™-, and DSP-compatible 4-wire serial interface
SMBus packet error checking (PEC) compatible
16-lead QSOP

APPLICATIONS

Portable battery-powered instruments
Personal computers
Telecommunications systems
Electronic test equipment
Domestic appliances
Process control

PIN CONFIGURATION

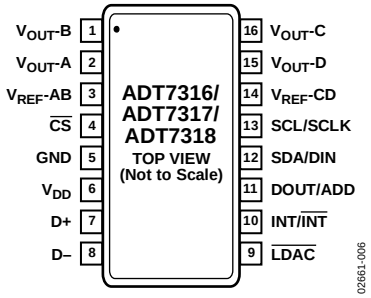

Figure 1.

GENERAL DESCRIPTION

The ADT7316/ADT7317/ADT7318[1] combine a 10-bit temperature-to-digital converter and a quad 12-/10-/8-bit DAC, respectively, in a 16-lead QSOP. This includes a band gap temperature sensor and a 10-bit ADC to monitor and digitize the temperature reading to a resolution of 0.25°C. The ADT7316/ ADT7317/ADT7318 operate from a single 2.7 V to 5.5 V supply. The output voltage of the DAC ranges from 0 V to 2 V_{REF}, with an output voltage settling time of 7 µs typically. The ADT7316/ ADT7317/ADT7318 provide two serial interface options, a 4-wire serial interface that is compatible with SPI, QSPI, MICROWIRE, and DSP interface standards, and a 2-wire SMBus/I²C interface. They feature a standby mode that is controlled via the serial interface.

The reference for the four DACs is derived either internally or from two reference pins (one per DAC pair). The outputs of all DACs may be updated simultaneously using the software LDAC function or external $\overline{LDAC}$ pin. The ADT7316/ADT7317/ADT7318 incorporate a power-on-reset circuit that ensures the DAC output powers up to 0 V and remains there until a valid write takes place.

The ADT7316/ADT7317/ADT7318 wide supply voltage range, low supply current, and SPI-/I²C-compatible interface make them ideal for a variety of applications, including personal computers, office equipment, and domestic appliances.

[1] Protected by the following U.S. patent numbers: 5,764,174; 5,867,012; 6,097,239; 6,169,442. Other patents pending.

Rev. B
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SPECIFICATIONS

Temperature ranges for A version: −40°C to +120°C. V_{DD} = 2.7 V to 5.5 V, GND = 0 V, REFIN = 2.25 V, unless otherwise noted.

Table 1.

Parameter[1]	Min	Typ	Max	Unit	Conditions/Comments
DAC DC PERFORMANCE[2, 3]					
ADT7318					
Resolution		8		Bits	
Relative Accuracy		±0.15	±1	LSB	
Differential Nonlinearity		±0.02	±0.25	LSB	Guaranteed monotonic over all codes.
ADT7317					
Resolution		10		Bits	
Relative Accuracy		±0.5	±4	LSB	
Differential Nonlinearity		±0.05	±0.5	LSB	Guaranteed monotonic over all codes.
ADT7316					
Resolution		12		Bits	
Relative Accuracy		±2	±16	LSB	
Differential Nonlinearity		±0.02	±0.9	LSB	Guaranteed monotonic over all codes.
Offset Error		±0.4	±2	% of FSR	
Gain Error		±0.4	±2	% of FSR	
Lower Dead Band		20	65	mV	Lower dead band exists only if offset error is negative. See Figure 2.
Upper Dead Band		60	100	mV	Upper dead band exists if $V_{REF} = V_{DD}$ and offset plus gain error is positive. See Figure 3.
Offset Error Drift		−12		ppm of FSR/°C	
Gain Error Drift		−5		ppm of FSR/°C	
DC Power Supply Rejection Ratio		−60		dB	ΔV_{DD} = ±10%.
DC Crosstalk		200		µV	See Figure 6.
THERMAL CHARACTERISTICS					Internal reference used. Averaging on.
INTERNAL TEMPERATURE SENSOR					
Accuracy at V_{DD} = 3.3 V ±10%			±1.5	°C	T_A = 85°C.
		±0.5	±3	°C	T_A = 0°C to +85°C.
		±2	±5	°C	T_A = −40°C to +120°C.
Accuracy at V_{DD} = 5 V ±5%		±2	±3	°C	T_A = 0°C to +85°C.
		±3	±5	°C	T_A = −40°C to +120°C.
Resolution			10	Bits	Equivalent to 0.25°C.
Long-Term Drift		0.25		°C	Drift over 10 years if part is operated at 55°C.
EXTERNAL TEMPERATURE SENSOR					External transistor = 2N3906.
Accuracy at V_{DD} = 3.3 V ±10%			±1.5	°C	T_A = +85°C.
			±3	°C	T_A = 0°C to +85°C.
			±5	°C	T_A = −40°C to +120°C.
Accuracy at V_{DD} = 5 V ±5%		±2	±3	°C	T_A = 0°C to +85°C.
		±3	±5	°C	T_A = −40°C to +120°C.
Resolution			10	Bits	Equivalent to +0.25°C.
Output Source Current		180		µA	High level.
		11		µA	Low level.
Thermal Voltage Output					
8-Bit DAC Output					
Resolution	1			°C	
Scale Factor		8.79		mV/°C	0 V to V_{REF} output. T_A = −40°C to +120°C.
		17.58		mV/°C	0 V to 2 V_{REF} output. T_A = −40°C to +120°C.
10-Bit DAC Output					
Resolution	0.25			°C	
Scale Factor		2.2		mV/°C	0 V to V_{REF} output. T_A = −40°C to +120°C.
		4.39		mV/°C	0 V to 2 V_{REF} output. T_A= −40°C to +120°C.

Parameter[1]	Min	Typ	Max	Unit	Conditions/Comments
CONVERSION TIMES					Single channel mode.
Slow ADC					
V_{DD}		11.4		ms	Averaging (16 samples) on.
		712		µs	Averaging off.
Internal Temperature		11.4		ms	Averaging (16 samples) on.
		712		µs	Averaging off.
External Temperature		24.22		ms	Averaging (16 samples) on
		1.51		ms	Averaging off.
Fast ADC					
V_{DD}		712		µs	Averaging (16 samples) on.
		44.5		µs	Averaging off.
Internal Temperature		2.14		ms	Averaging (16 samples) on.
		134		µs	Averaging off.
External Temperature		14.25		ms	Averaging (16 samples) on.
		890		µs	Averaging off.
ROUND ROBIN UPDATE RATE[4]					Time to complete one measurement cycle through all channels.
Slow ADC at 25°C					
		59.95		ms	Averaging on.
		6.52		ms	Averaging off.
Fast ADC at 25°C					
		19.59		ms	Averaging on.
		2.89		ms	Averaging off.
DAC EXTERNAL REFERENCE INPUT[5]					
V_{REF} Input Range	1		V_{DD}	V	Buffered reference mode.
V_{REF} Input Range	0.25		V_{DD}	V	Unbuffered reference mode.
V_{REF} Input Impedance	37	45		kΩ	Unbuffered reference mode. 0 V to 2 V_{REF} output range.
	74	90		kΩ	Unbuffered reference mode. 0 V to V_{REF} output range.
		>10		MΩ	Buffered reference mode and power-down mode.
Reference Feedthrough		−90		dB	Frequency = 10 kHz.
Channel-to-Channel Isolation		−75		dB	Frequency = 10 kHz.
ON-CHIP REFERENCE					
Reference Voltage[5]	2.2662	2.28	2.2938	V	
Temperature Coefficient[5]		80		ppm/°C	
OUTPUT CHARACTERISTICS[5]					
Output Voltage[6]	0.001		V_{DD} to 0.001	V	This is a measure of the minimum and maximum drive capability of the output amplifier.
DC Output Impedance		0.5		Ω	
Short-Circuit Current		25		mA	V_{DD} = 5 V.
		16		mA	V_{DD} = 3 V.
Power-Up Time		2.5		µs	Coming out of power-down mode. V_{DD} = 5 V.
		5		µs	Coming out of power-down mode. V_{DD} = 3.3 V.
DIGITAL INPUTS[5]					
Input Current			±1	µA	V_{IN} = 0 V to V_{DD}.
Input Low Voltage, V_{IL}			0.8	V	
Input High Voltage, V_{IH}	1.89			V	
Pin Capacitance		3	10	pF	All digital inputs.
SCL, SDA Glitch Rejection			50	ns	Input filtering suppresses noise spikes of less than 50 ns.
$\overline{\text{LDAC}}$ Pulse Width	20			ns	Edge triggered input.

Parameter[1]	Min	Typ	Max	Unit	Conditions/Comments
DIGITAL OUTPUT					
Output High Voltage, V_{OH}	2.4			V	$I_{SOURCE} = I_{SINK} = 200$ µA.
Output Low Voltage, V_{OL}			0.4	V	$I_{OL} = 3$ mA.
Output High Current, I_{OH}			1	mA	$V_{OH} = 5$ V.
Output Capacitance, C_{OUT}			50	pF	
INT/$\overline{\text{INT}}$ Output Saturation Voltage			0.8	V	$I_{OUT} = 4$ mA.
I^2C TIMING CHARACTERISTICS[7, 8]					
Serial Clock Period, t_1	2.5			µs	Fast-mode I^2C. See Figure 4.
Data In Setup Time to SCL High, t_2	50			ns	
Data Out Stable After SCL Low, t_3	0			ns	See Figure 4.
SDA Low Setup Time to SCL Low (Start Condition), t_4	50			ns	See Figure 4.
SDA High Hold Time After SCL High (Stop Condition), t_5	50			ns	See Figure 4.
SDA and SCL Fall Time, t_6			300	ns	See Figure 4.
SDA and SCL Rise Time, t_6			300[9]	ns	See Figure 4.
SPI TIMING CHARACTERISTICS[10, 11]					
$\overline{\text{CS}}$ to SCLK Setup Time, t_1	0			ns	See Figure 7.
SCLK High Pulse Width, t_2	50			ns	See Figure 7.
SCLK Low Pulse Width, t_3	50			ns	See Figure 7.
Data Access Time After SCLK Falling Edge, t_4[12]			35	ns	See Figure 7.
Data Setup Time Prior to SCLK Rising Edge, t_5	20			ns	See Figure 7.
Data Hold Time after SCLK Rising Edge, t_6	0			ns	See Figure 7.
$\overline{\text{CS}}$ to SCLK Hold Time, t_7	0			ns	See Figure 7.
$\overline{\text{CS}}$ to DOUT High Impedance, t_8			40	ns	See Figure 7.
POWER REQUIREMENTS					
V_{DD}	2.7		5.5	V	
V_{DD} Settling Time			50	ms	V_{DD} settles to within 10% of its final voltage level.
I_{DD} (Normal Mode)[13]			3	mA	$V_{DD} = 3.3$ V, $V_{IH} = V_{DD}$, and V_{IL} = GND.
		2.2	3	mA	$V_{DD} = 5$ V, $V_{IH} = V_{DD}$, and V_{IL} = GND.
I_{DD} (Power-Down Mode)			10	µA	$V_{DD} = 3.3$ V, $V_{IH} = V_{DD}$, and V_{IL} = GND.
			10	µA	$V_{DD} = 5$ V, $V_{IH} = V_{DD}$, and V_{IL} = GND.
Power Dissipation			10	mW	$V_{DD} = 3.3$ V, using normal mode.
			33	µW	$V_{DD} = 3.3$ V, using shutdown mode.

[1] See the Terminology section.
[2] DC specifications tested with the outputs unloaded.
[3] Linearity is tested using a reduced code range: ADT7316 (Code 115 to 4095); ADT7317 (Code 28 to 1023); ADT7318 (Code 8 to 255).
[4] A round robin is the continuous sequential measurement of the following three channels: V_{DD}, internal temperature, and external temperature.
[5] Guaranteed by design and characterization, but not production tested.
[6] For the amplifier output to reach its minimum voltage, the offset error must be negative. For the amplifier output to reach its maximum voltage, $V_{REF} = V_{DD}$, offset plus gain error must be positive.
[7] The SDA and SCL timing is measured with the input filters turned on to meet the fast-mode I^2C specification. Switching off the input filters improves the transfer rate, but has a negative effect on the EMC behavior of the part.
[8] Guaranteed by design. Not tested in production.
[9] The interface is also capable of handling the I^2C standard mode rise time specification of 1000 ns.
[10] Guaranteed by design and characterization, but not production tested.
[11] All input signals are specified with tr = tf = 5 ns (10% to 90% of V_{DD}) and timed from a voltage level of 1.6 V.
[12] Measured with the load circuit of Figure 5.
[13] I_{DD} specification is valid for all DAC codes. Interface inactive. All DACs active. Load currents excluded.

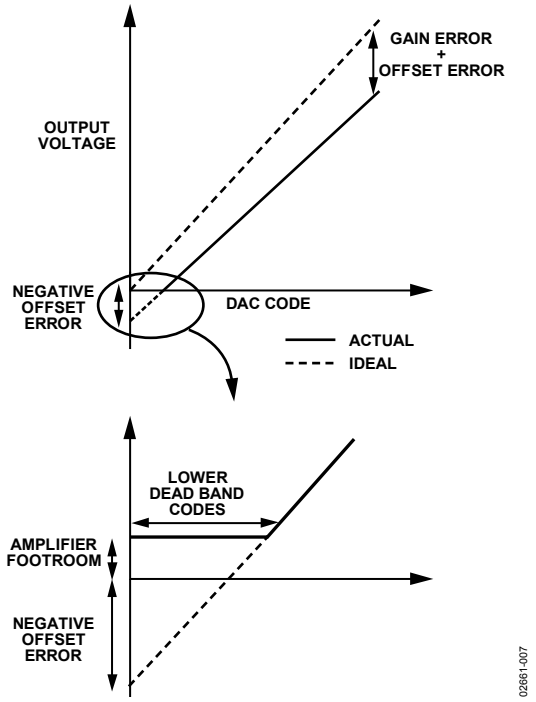

Figure 2. DAC Transfer Function with Negative Offset

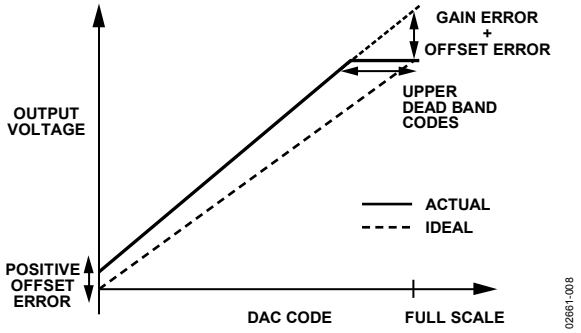

Figure 3. DAC Transfer Function with Positive Offset ($V_{REF} = V_{DD}$)

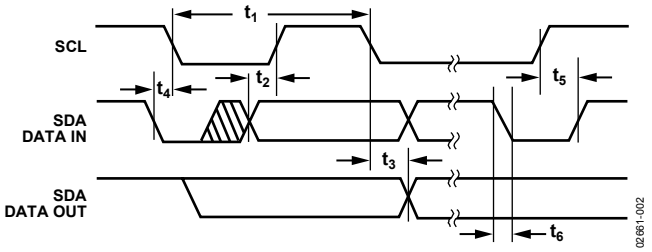

Figure 4. I²C Bus Timing Diagram

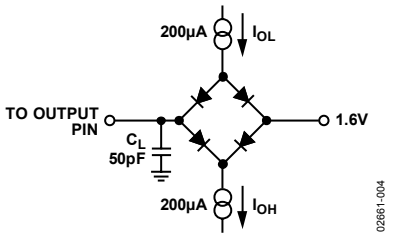

Figure 5. Load Circuit for Access Time and Bus Relinquish Time

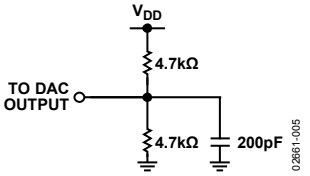

Figure 6. Load Circuit for DAC Outputs

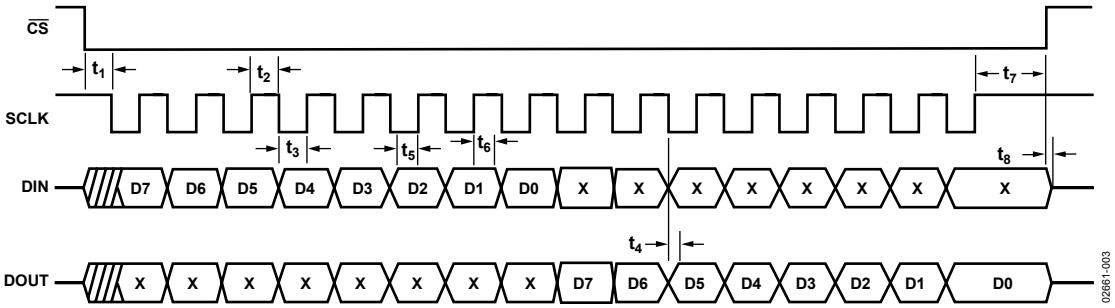

Figure 7. SPI Bus Timing Diagram

FUNCTIONAL BLOCK DIAGRAM

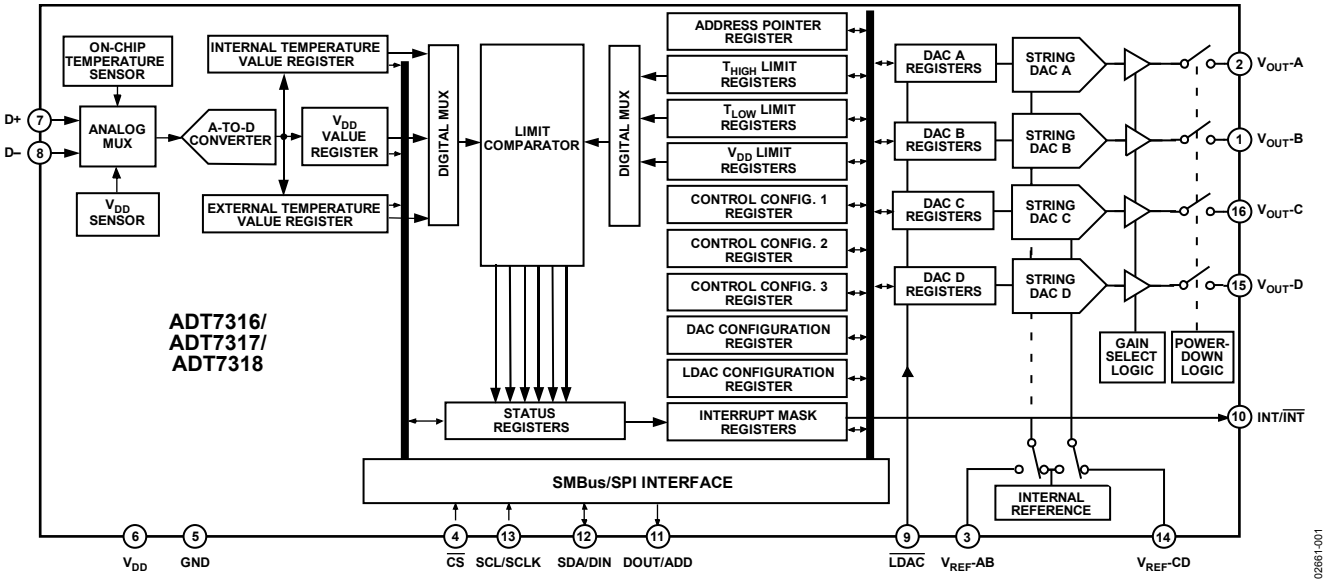

Figure 8.

DAC AC CHARACTERISTICS

Guaranteed by design and characterization, but not production tested. V_{DD} = 2.7 V to 5.5 V; R_L = 4.7 kΩ to GND; C_L = 200 pF to GND; 4.7 kΩ to V_{DD}. All specifications T_{MIN} to T_{MAX}, unless otherwise noted.

Table 2.

Parameter[1]	Min	Typ (@ 25°C)	Max	Unit	Conditions and Comments
Output Voltage Settling Time					$V_{REF} = V_{DD}$ = +5 V.
ADT7318		6	8	µs	1/4 scale to 3/4 scale change (0x40 to 0xC0).
ADT7317		7	9	µs	1/4 scale to 3/4 scale change (0x100 to 0x300).
ADT7316		8	10	µs	1/4 scale to 3/4 scale change (0x400 to 0xC00).
Slew Rate		0.7		V/µs	
Major-Code Change Glitch Energy		12		nV-s	1 LSB change around major carry.
Digital Feedthrough		0.5			
Digital Crosstalk		1		nV-s	
Analog Crosstalk		0.5		nV-s	
DAC-to-DAC Crosstalk		3		nV-s	
Multiplying Bandwidth		200		kHz	V_{REF} = 2 V ± 0.1 V p-p.
Total Harmonic Distortion		−70		dB	V_{REF} = 2.5 V ± 0.1 V p-p. Frequency = 10 kHz.

[1] See Terminology section.

ABSOLUTE MAXIMUM RATINGS

Table 3.

Parameter	Rating
V_{DD} to GND	−0.3 V to +7 V
Digital Input Voltage to GND	−0.3 V to V_{DD} + 0.3 V
Digital Output Voltage to GND	−0.3 V to V_{DD} + 0.3 V
Reference Input Voltage to GND	−0.3 V to V_{DD} + 0.3 V
Operating Temperature Range	−40°C to +120°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature	
16-Lead QSOP	150°C
Power Dissipation[1]	(T_J max − T_A)/θ_{JA}
Thermal Impedance[2]	
θ_{JA} Junction-to-Ambient	105.44°C/W
θ_{JC} Junction-to-Case	38.8°C/W
IR Reflow Soldering	
Peak Temperature	220°C (0/5°C)
Time at Peak Temperature	10 sec to 20 sec
Ramp-Up Rate	2°C/sec to 3°C/sec
Ramp-Down Rate	−6°C/sec
IR Reflow Soldering (Pb-Free Package)	
Peak Temperature	260°C (+ 0°C)
Time at Peak Temperature	20 sec to 40 sec
Ramp-Up Rate	3°C/sec maximum
Ramp-Down Rate	−6°C/sec maximum
Time 25°C to Peak Temperature	8 minutes maximum

[1] Values relate to package being used on a 4-layer board.
[2] Junction-to-case resistance is applicable to components featuring a preferential flow direction, for example, components mounted on a heat sink. Junction-to-ambient resistance is more useful for air-cooled, PCB-mounted components.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 4. I²C Address Selection

ADD Pin	I²C Address
Low	1001 000
Float	1001 010
High	1001 011

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

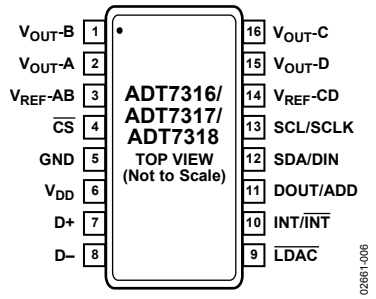

Figure 9. Pin Configuration QSOP

Table 5. Pin Function Descriptions

Pin No.	Mnemonic	Description
1	V_{OUT}-B	Buffered Analog Output Voltage from DAC B. The output amplifier has rail-to-rail operation.
2	V_{OUT}-A	Buffered Analog Output Voltage from DAC A. The output amplifier has rail-to-rail operation.
3	V_{REF}-AB	Reference Input Pin for DAC A and DAC B. It may be configured as a buffered or unbuffered input to both DAC A and DAC B. It has an input range from 0.25 V to V_{DD} in unbuffered mode and from 1 V to V_{DD} in buffered mode. DAC A and DAC B default on power-up to this pin.
4	$\overline{CS}$	SPI Active Low Control Input. This is the frame synchronization signal for the input data. When $\overline{CS}$ goes low, it enables the input register, and data is transferred in on the rising edges and out on the falling edges of the subsequent serial clocks. It is recommended that this pin be tied high to V_{DD} when operating the serial interface in I^2C mode.
5	GND	Ground Reference Point for All Circuitry on the Part. Analog and digital ground.
6	V_{DD}	Positive Supply Voltage, 2.7 V to 5.5 V. The supply should be decoupled to ground.
7	D+	Positive connection to external temperature sensor.
8	D–	Negative connection to external temperature sensor.
9	$\overline{LDAC}$	Active low control input that transfers the contents of the input registers to their respective DAC registers. A falling edge on this pin forces any or all DAC registers to be updated if the input registers have new data. A minimum pulse width of 20 ns must be applied to the $\overline{LDAC}$ pin to ensure proper loading of a DAC register. This allows simultaneous update of all DAC outputs. Bit C3 of the Control Configuration 3 register enables the $\overline{LDAC}$ pin. Default is with the $\overline{LDAC}$ pin controlling the loading of DAC registers.
10	INT/$\overline{INT}$	Over-Limit Interrupt. The output polarity of this pin can be set to give an active low or active high interrupt when temperature or V_{DD} limits are exceeded. Default is active low. Open-drain output—needs a pull-up resistor.
11	DOUT/ADD	DOUT: SPI Serial Data Output. Logic output. Data is clocked out of any register at this pin. Data is clocked out on the falling edge of SCLK. Open-drain output—needs a pull-up resistor. ADD: I^2C Serial Bus Address Selection Pin. Logic input. A low on this pin gives the address 1001 000, leaving it floating gives the address 1001 010, and setting it high gives the address 1001 011. The I^2C address set up by the ADD pin is not latched by the device until after this address has been sent twice. On the eighth SCL cycle of the second valid communication, the serial bus address is latched in. Any subsequent changes on this pin have no affect on the I^2C serial bus address.
12	SDA/DIN	SDA: I^2C Serial Data Input. I^2C serial data that is loaded into the device registers is provided on this input. Open-drain configuration—needs a pull-up resistor. DIN: SPI Serial Data Input. Serial data to be loaded into the device registers is provided on this input. Data is clocked into a register on the rising edge of SCLK. Open-drain configuration—needs a pull-up resistor.
13	SCL/SCLK	Serial Clock Input. This is the clock input for the serial port. The serial clock is used to clock data out of any register of the ADT7316/ADT7317/ADT7318 and also to clock data into any register that can be written to. Open-drain configuration; needs a pull-up resistor.
14	V_{REF}-CD	Reference Input Pin for DAC C and DAC D. It can be configured as a buffered or unbuffered input to both DAC C and DAC D. It has an input range from 0.25 V to V_{DD} in unbuffered mode and from 1 V to V_{DD} in buffered mode. DAC C and DAC D default, on power-up, to this pin.
15	V_{OUT}-D	Buffered Analog Output Voltage from DAC D. The output amplifier has rail-to-rail operation.
16	V_{OUT}-C	Buffered Analog Output Voltage from DAC C. The output amplifier has rail-to-rail operation.

TERMINOLOGY

Relative Accuracy
Relative accuracy or integral nonlinearity (INL) is a measure of the maximum deviation, in LSBs, from a straight line passing through the endpoints of the DAC transfer function. Typical INL vs. code plots can be seen in Figure 10, Figure 11, and Figure 12.

Differential Nonlinearity (DNL)
Differential nonlinearity is the difference between the measured change and the ideal 1 LSB change between any two adjacent codes. A specified differential nonlinearity of ±0.9 LSB maximum ensures monotonicity. Typical DAC DNL vs. code plots can be seen in Figure 13, Figure 14, and Figure 15.

Offset Error
This is a measure of the offset error of the DAC and the output amplifier (see Figure 2 and Figure 3). It can be negative or positive. It is expressed as a percentage of the full-scale range.

Gain Error
This is a measure of the span error of the DAC. It is the deviation in slope of the actual DAC transfer characteristic from the ideal. It is expressed as a percentage of the full-scale range.

Offset Error Drift
This is a measure of the change in offset error with changes in temperature. It is expressed in ppm of full-scale range/°C.

Gain Error Drift
This is a measure of the change in gain error with changes in temperature. It is expressed in ppm of full-scale range/°C.

Long Term Temperature Drift
This is a measure of the change in temperature error with the passage of time. It is expressed in degrees Celsius. The concept of long term stability has been used for many years to describe by what amount an IC's parameter would shift during its lifetime. This is a concept that has been typically applied to both voltage references and monolithic temperature sensors. Unfortunately, integrated circuits cannot be evaluated at room temperature (25°C) for 10 years or so to determine this shift. As a result, manufacturers very typically perform accelerated lifetime testing of integrated circuits by operating ICs at elevated temperatures (between 125°C and 150°C) over a shorter period of time (typically between 500 and 1000 hours). As a result of this operation, the lifetime of an integrated circuit is significantly accelerated due to the increase in rates of reaction within the semiconductor material.

DC Power Supply Rejection Ratio (PSRR)
This indicates how the output of the DAC is affected by changes in the supply voltage. PSRR is the ratio of the change in V_{OUT} to a change in V_{DD} for full-scale output of the DAC. It is measured in decibels. V_{REF} is held at 2 V and V_{DD} is varied ±10%.

DC Crosstalk
This is the dc change in the output level of one DAC in response to a change in the output of another DAC. It is measured with a full-scale output change on one DAC while monitoring another DAC. It is expressed in microvolts.

Reference Feedthrough
This is the ratio of the amplitude of the signal at the DAC output to the reference input when the DAC output is not being updated (that is, $\overline{\text{LDAC}}$ is high). It is expressed in decibels.

Channel-to-Channel Isolation
This is the ratio of the amplitude of the signal at the output of one DAC to a sine wave on the reference input of another DAC. It is measured in decibels.

Major-Code Transition Glitch Energy
Major-code transition glitch energy is the energy of the impulse injected into the analog output when the code in the DAC register changes state. It is normally specified as the area of the glitch in nV-s and is measured when the digital code is changed by 1 LSB at the major carry transition (011…11 to 100…00 or 100...00 to 011…11).

Digital Feedthrough
Digital feedthrough is a measure of the impulse injected into the analog output of a DAC from the digital input pins of the device but is measured when the DAC is not being written to. It is specified in nV-s and is measured with a full-scale change on the digital input pins, that is, from all 0s to all 1s or vice versa.

Digital Crosstalk
This is the glitch impulse transferred to the output of one DAC at midscale in response to a full-scale code change (all 0s to all 1s and vice versa) in the input register of another DAC. It is measured in standalone mode and is expressed in nV-s.

Analog Crosstalk
This is the glitch impulse transferred to the output of one DAC due to a change in the output of another DAC. It is measured by loading one of the input registers with a full-scale code change (all 0s to all 1s and vice versa) while keeping $\overline{\text{LDAC}}$ high. Pulse $\overline{\text{LDAC}}$ low and monitor the output of the DAC whose digital code was not changed. The area of the glitch is expressed in nV-s.

DAC-to-DAC Crosstalk
This is the glitch impulse transferred to the output of one DAC due to a digital code change and subsequent output change of another DAC. This includes both digital and analog crosstalk. It is measured by loading one of the DACs with a full-scale code change (all 0s to all 1s and vice versa) with $\overline{\text{LDAC}}$ low and monitoring the output of another DAC. The energy of the glitch is expressed in nV-s.

Multiplying Bandwidth
The amplifiers within the DAC have a finite bandwidth. The multiplying bandwidth is a measure of this. A sine wave on the reference (with full-scale code loaded to the DAC) appears on the output. The multiplying bandwidth is the frequency at which the output amplitude falls to 3 dB below the input.

Total Harmonic Distortion
This is the difference between an ideal sine wave and its attenuated version using the DAC. The sine wave is used as the reference for the DAC, and the THD is a measure of the harmonics present on the DAC output. It is measured in decibels.

Round Robin
This term is used to describe the ADT7316/ADT7317/ADT7318 cycling through the available measurement channels in sequence, taking a measurement on each channel.

DAC Output Settling Time
This is the time required, following a prescribed data change, for the output of a DAC to reach and remain within ±0.5 LSB of the final value. A typical prescribed change is from 1/4 scale to 3/4 scale.

TYPICAL PERFORMANCE CHARACTERISTICS

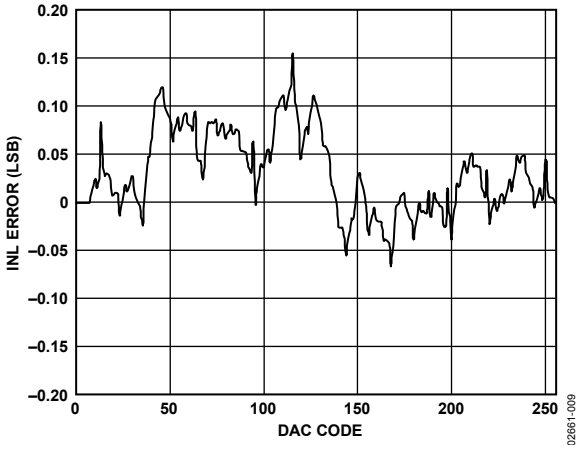

Figure 10. ADT7318 Typical INL Plot

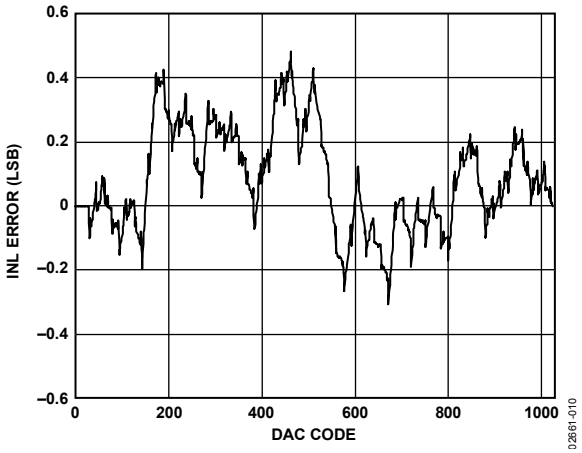

Figure 11. ADT7317 Typical INL Plot

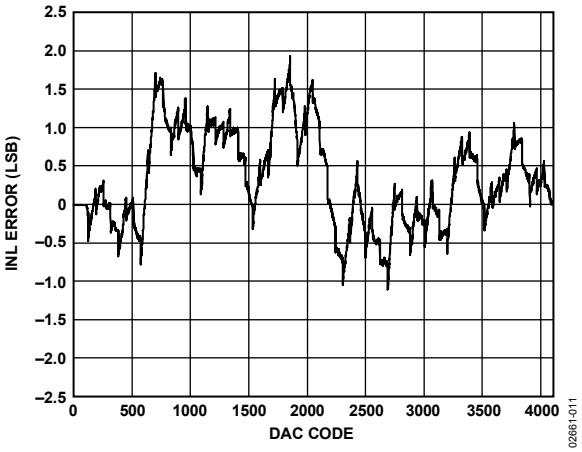

Figure 12. ADT7316 Typical INL Plot

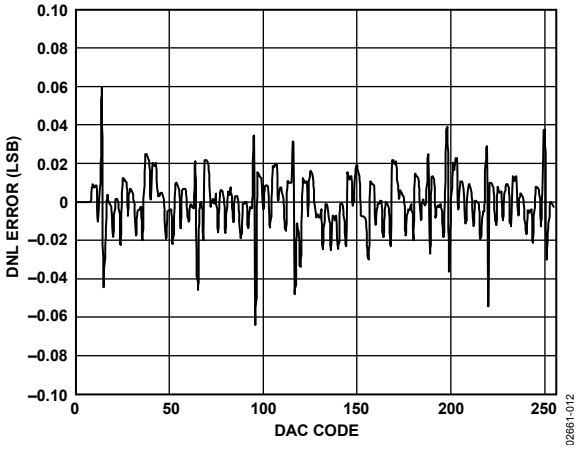

Figure 13. ADT7318 Typical DNL Plot

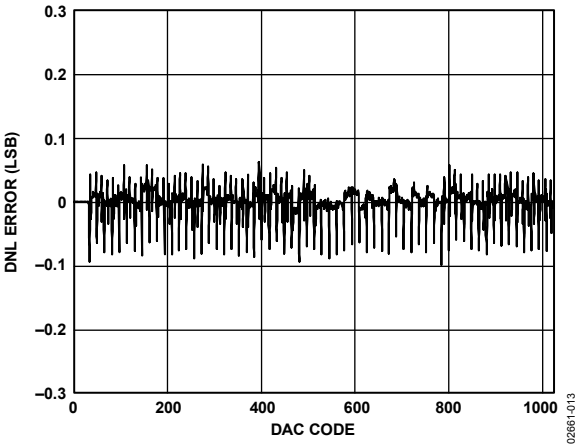

Figure 14. ADT7317 Typical DNL Plot

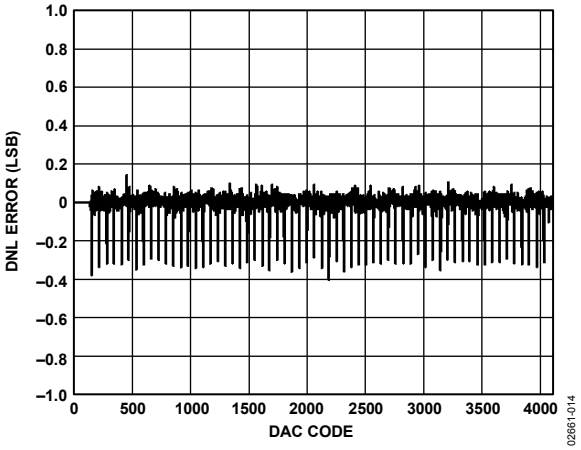

Figure 15. ADT7316 Typical DNL Plot

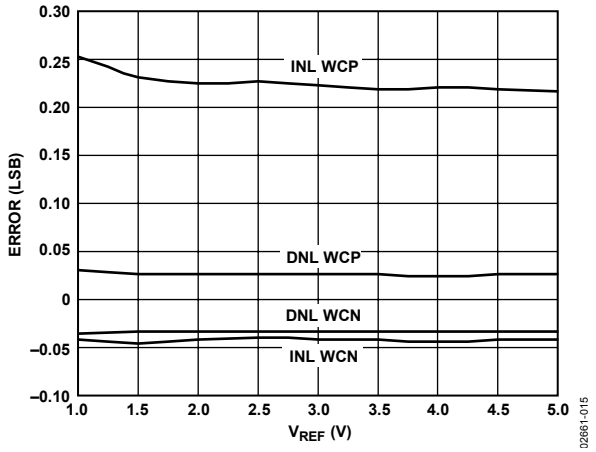

Figure 16. ADT7318 INL Error and DNL Error vs. V_{REF}

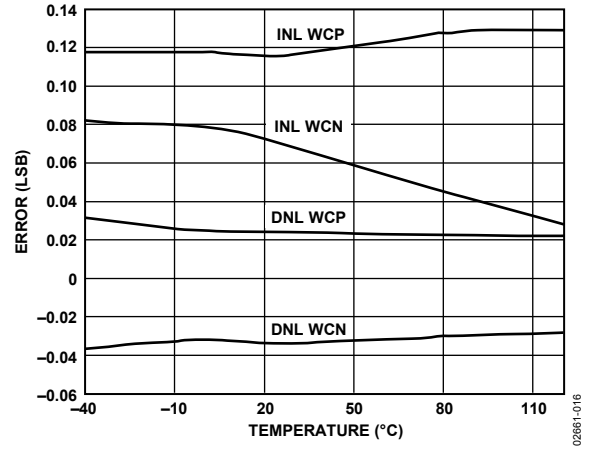

Figure 17. ADT7318 INL Error and DNL Error vs. Temperature

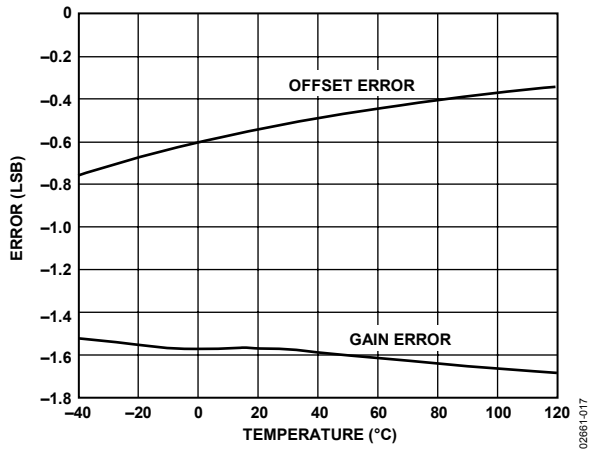

Figure 18. Offset Error and Gain Error vs. Temperature

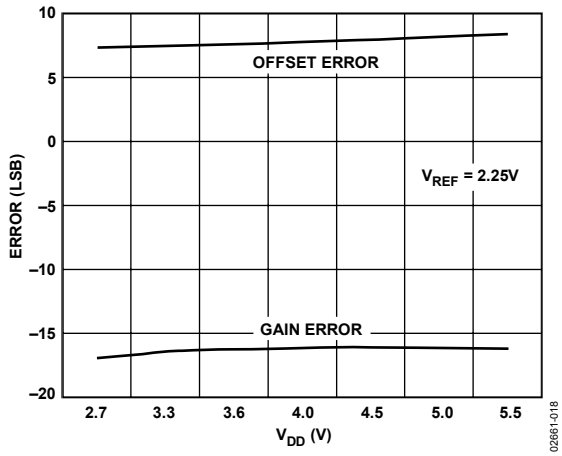

Figure 19. Offset Error and Gain Error vs. V_{DD}

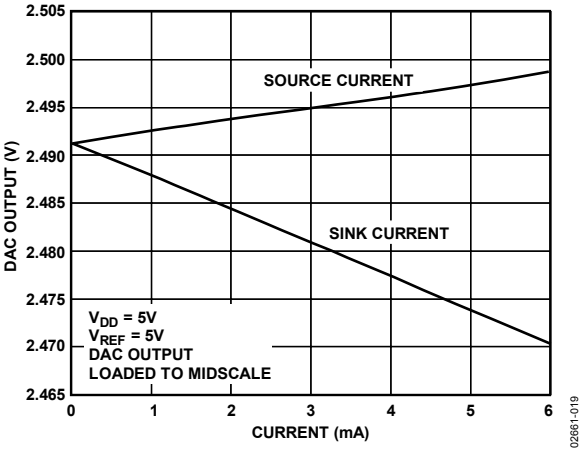

Figure 20. V_{OUT} Source and Sink Current Capability

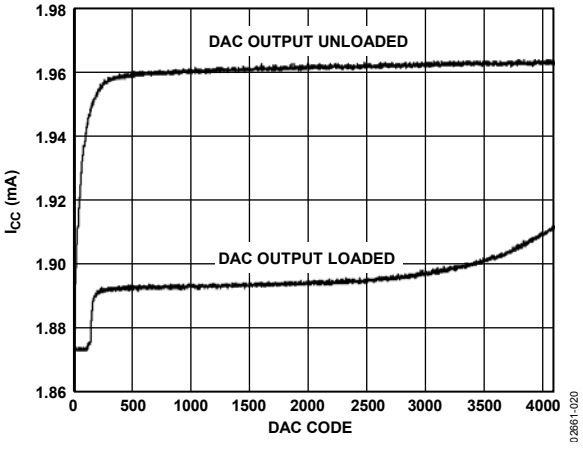

Figure 21. Supply Current vs. DAC Code

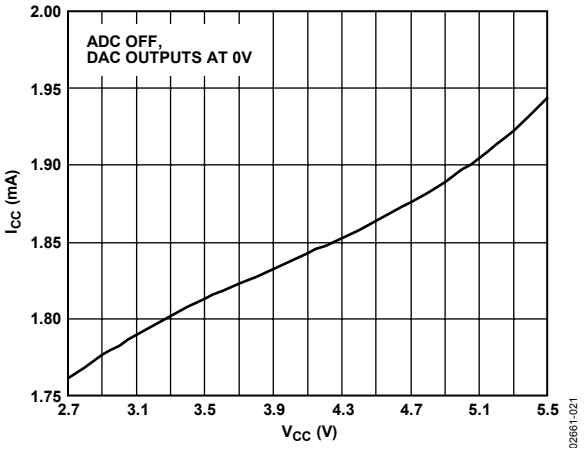

Figure 22. Supply Current vs. Supply Voltage @25°C

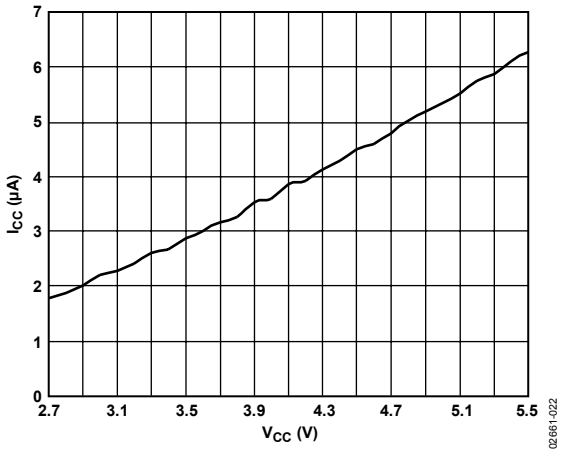

Figure 23. Power-Down Current vs. Supply Voltage @ 25°C

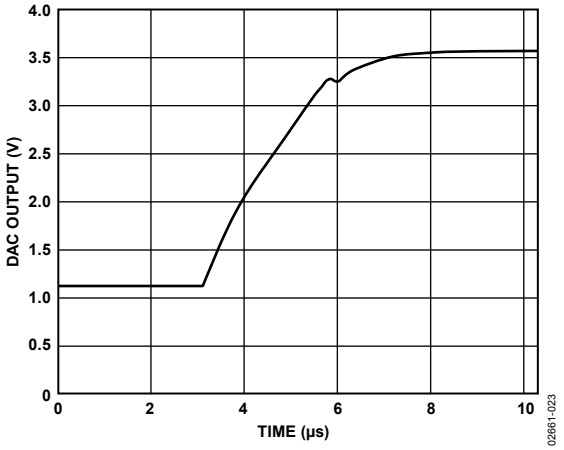

Figure 24. Half-Scale Settling (1/4 to 3/4 Scale Code Change)

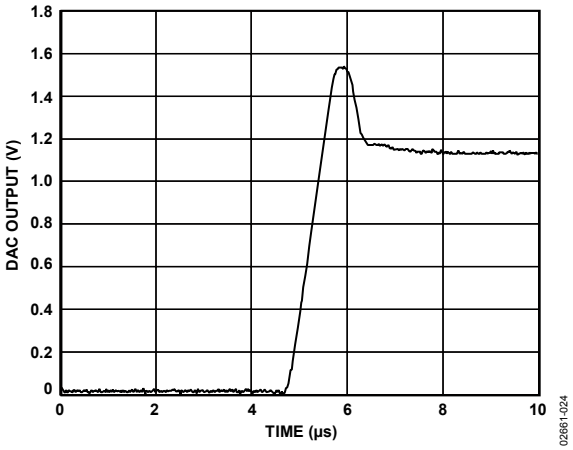

Figure 25. Exiting Power-Down to Midscale

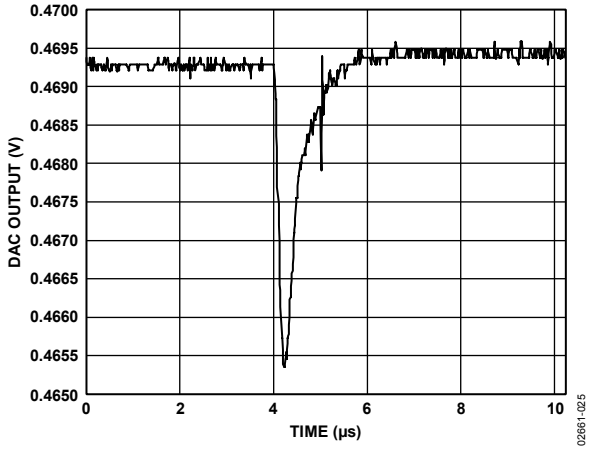

Figure 26. ADT7316 Major-Code Transition Glitch Energy (0….11 to 100…00)

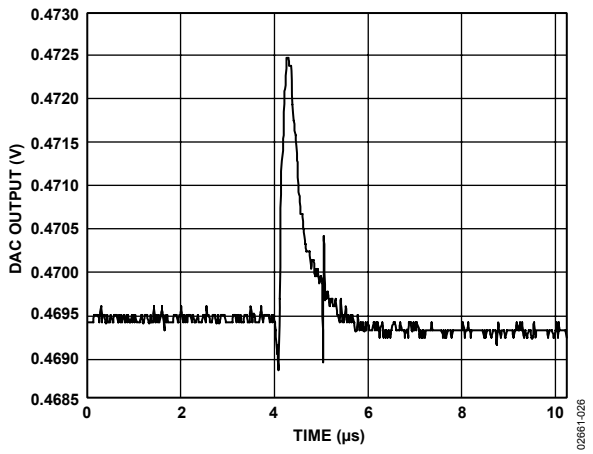

Figure 27. ADT7316 Major-Code Transition Glitch Energy (100…00 to 011…11)

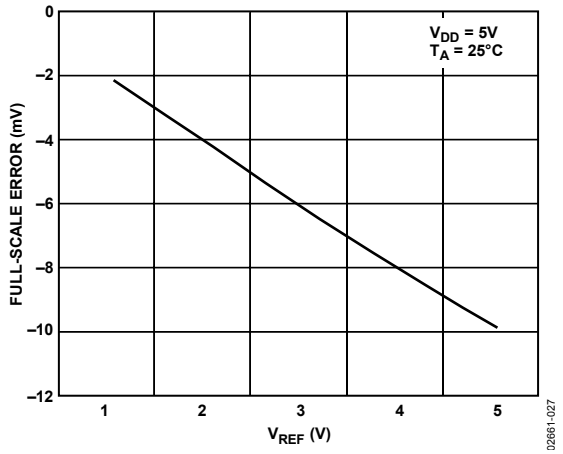

Figure 28. Full-Scale Error vs. V_{REF}

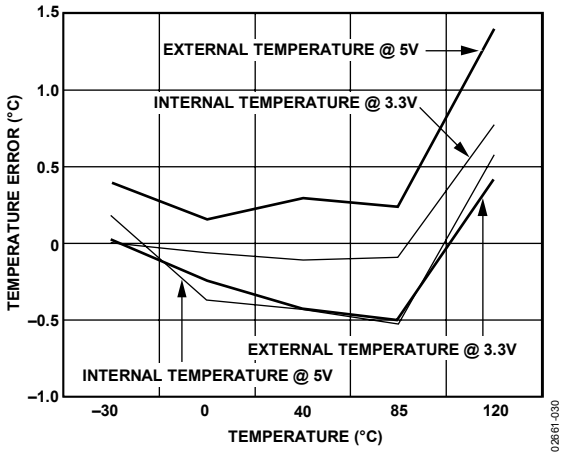

Figure 31. Temperature Error @ 3.3 V and 5 V

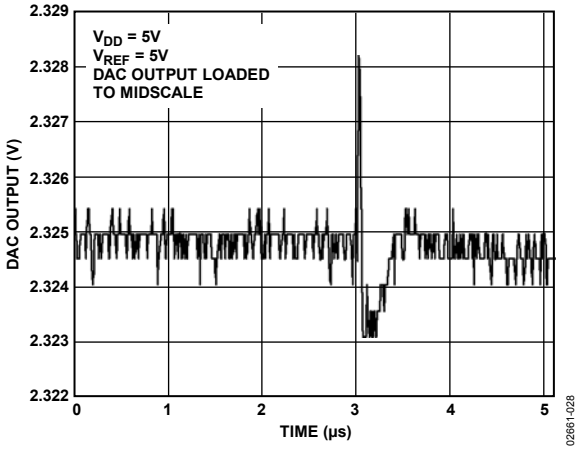

Figure 29. DAC-to-DAC Crosstalk

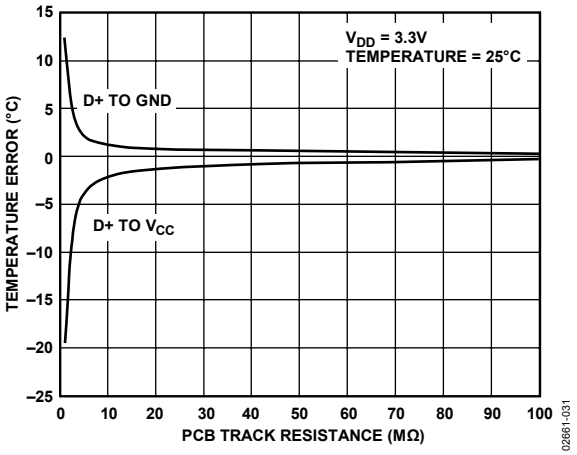

Figure 32. External Temperature Error vs. PCB Track Resistance

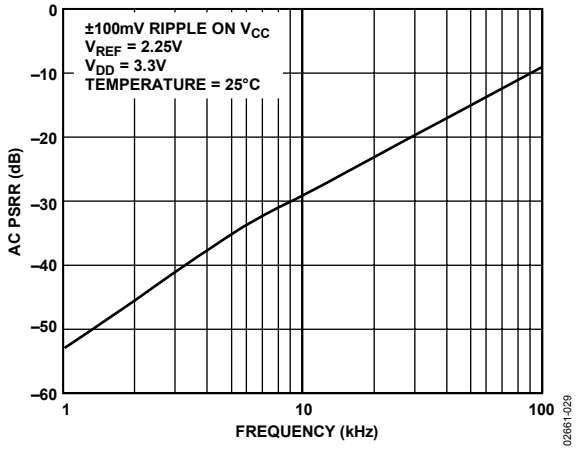

Figure 30. PSRR vs. Supply Ripple Frequency

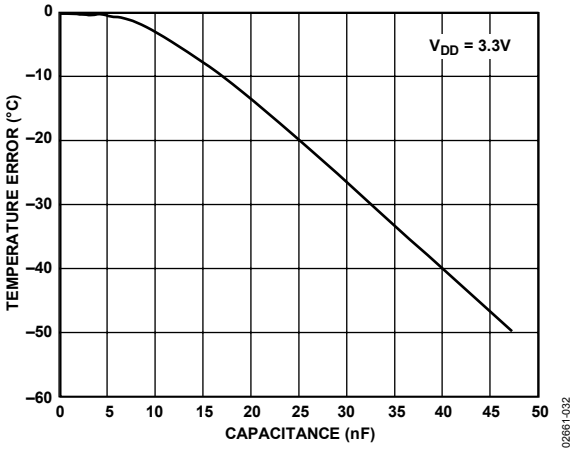

Figure 33. External Temperature Error vs. Capacitance Between D+ and D−

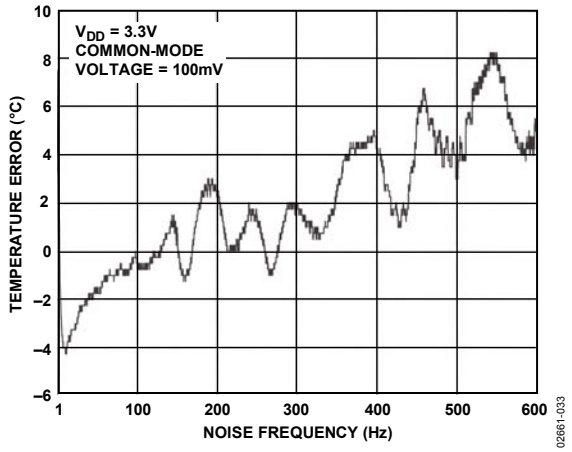

Figure 34. External Temperature Error vs. Common-Mode Noise Frequency

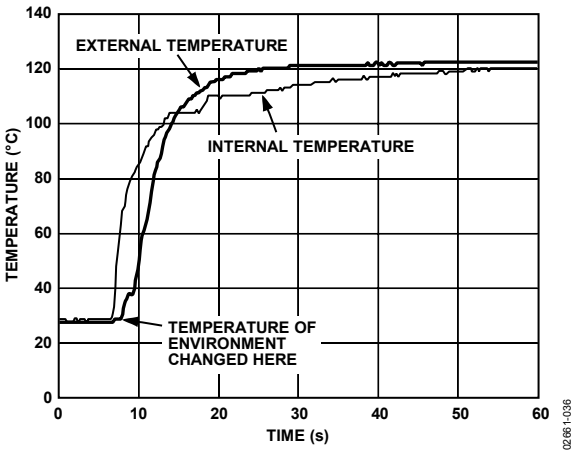

Figure 37. Temperature Sensor Response to Thermal Shock

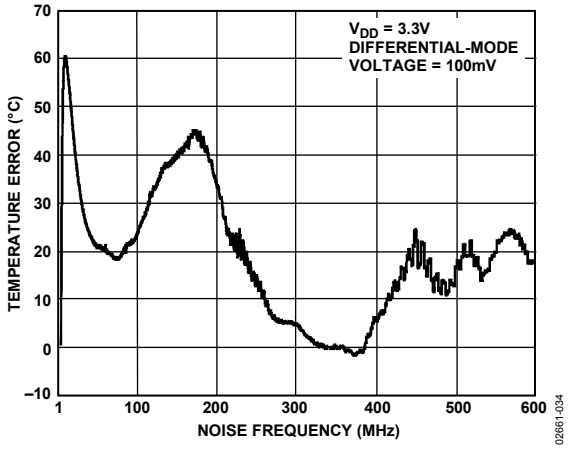

Figure 35. External Temperature Error vs. Differential-Mode Noise Frequency

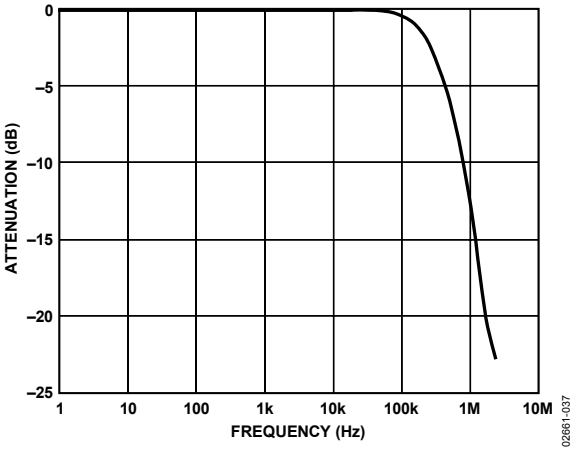

Figure 38. Multiplying Bandwidth (Small-Signal Frequency Response)

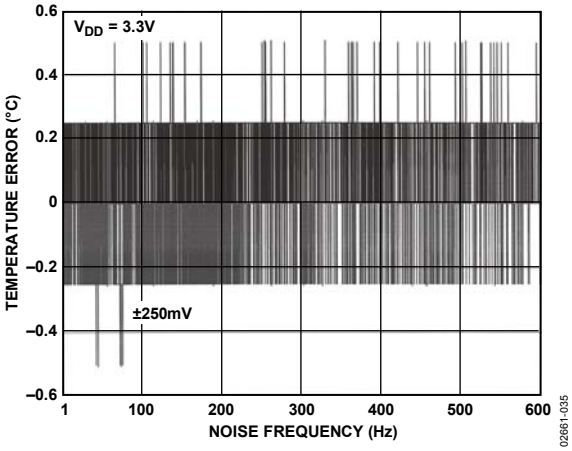

Figure 36. Internal Temperature Error vs. Power Supply Noise Frequency

THEORY OF OPERATION

Directly after the power-up calibration routine, the ADT7316/ADT7317/ADT7318 go into idle mode. In this mode, the device is not performing any measurements and is fully powered up. All four DAC outputs are at 0 V.

To begin monitoring, write to the Control Configuration 1 register (Address 0x18), and set Bit C0 = 1. The ADT7316/ADT7317/ADT7318 go into their power-up default measurement mode, which is round robin. The device proceeds to take measurements on the V_{DD} channel, the internal temperature sensor channel, and the external temperature sensor channel. Once it finishes taking measurements on the external temperature sensor channel, the device immediately loops back to start taking measurements on the V_{DD} channel and repeats the same cycle as before. This loop continues until the monitoring is stopped by resetting Bit C0 of the Control Configuration 1 register to 0.

It is also possible to continue monitoring as well as switching to single-channel mode by writing to the Control Configuration 2 register (Address 0x19) and setting Bit C4 = 1. Further explanation of the single-channel and round robin measurement modes is given in later sections. All measurement channels have averaging enabled on power-up. Averaging forces the device to take an average of 16 readings before giving a final measured result. To disable averaging and consequently decrease the conversion time by a factor of 16, set C5 = 1 in the Control Configuration 2 register.

Controlling the DAC outputs can be done by writing to the DAC MSB and LSB registers (Address 0x10 to Address 0x17). The power-up default setting is to have a low going pulse on the $\overline{\text{LDAC}}$ pin controlling the updating of the DAC outputs from the DAC registers. Alternatively, users can configure the updating of the DAC outputs to be controlled by means other than the $\overline{\text{LDAC}}$ pin by setting C3 = 1 of the Control Configuration 3 register (Address 0x1A). The DAC Configuration register (Address 0x1B), and the LDAC Configuration register (Address 0x1C) can then be used to control the DAC updating. These two registers also control the output range of the DACs, enabling or disabling the external reference buffer, and selecting between the internal or external reference. DAC A and DAC B outputs can be configured to give a voltage output proportional to the temperature of the internal and external temperature sensors, respectively.

The dual serial interface defaults to the I^2C protocol on power-up. To select and lock in the SPI protocol, follow the selection process as described in the Serial Interface Selection section. The I^2C protocol cannot be locked in, while the SPI protocol, when selected, is automatically locked in. The interface can only be switched back to be I^2C when the device is powered off and on. When using I^2C, the $\overline{\text{CS}}$ pin should be tied to either V_{DD} or GND.

There are a number of different operating modes on the ADT7316/ADT7317/ADT7318 devices, and all of them can be controlled by the configuration registers. These features consist of enabling and disabling interrupts, polarity of the INT/$\overline{\text{INT}}$ pin, enabling and disabling the averaging on the measurement channels, SMBus timeout, and software reset.

POWER-UP CALIBRATION

It is recommended that no communication to the part is initiated until approximately 5 ms after V_{DD} has settled to within 10% of its final value. It is generally accepted that most systems take a maximum of 50 ms to power-up. Power-up time is directly related to the amount of decoupling on the voltage supply line.

During the 5 ms after V_{DD} has settled, the part performs a calibration routine; any communication to the device interrupts this routine and can cause erroneous temperature measurements. If it is not possible to have V_{DD} at its nominal value by the time 50 ms has elapsed, or that communication to the device has started prior to V_{DD} settling, then it is recommended that a measurement be taken on the V_{DD} channel before a tempera ture measurement is taken. The V_{DD} measurement is used to calibrate out any temperature measurement error due to different supply voltage values.

CONVERSION SPEED

The internal oscillator circuit used by the ADC has the capability to output two different clock frequencies. This means that the ADC is capable of running at two different speeds when performing a conversion on a measurement channel. Thus, the time taken to perform a conversion on a channel can be reduced by setting C0 of Control Configuration 3 register (Address 0x1A). This increases the ADC clock speed from 1.4 kHz to 22 kHz. At the higher clock speed, the analog filters on the D+ and D− input pins (external temperature sensor) are switched off. This is why the power-up default setting is to have the ADC working at the slow speed. The typical times for fast and slow ADC speeds are given in the Specifications section.

The ADT7316/ADT7317/ADT7318 power up with averaging on. This means every channel is measured 16 times and internally averaged to reduce noise. The conversion time can also be sped up by turning the averaging off; to do so, set Bit C5 of the Control Configuration 2 register (Address 0x19) to 1.

FUNCTIONAL DESCRIPTION—VOLTAGE OUTPUT

DIGITAL-TO-ANALOG CONVERTERS

The ADT7316/ADT7317/ADT7318 have four resistor-string DACs fabricated on a CMOS process, with resolutions of 12, 10, and 8 bits, respectively. They contain four output buffer amplifiers and are written to via an I²C serial interface or an SPI serial interface. See the Serial Interface Selection section for more information.

The ADT7316/ADT7317/ADT7318 operate from a single supply of 2.7 V to 5.5 V, and the output buffer amplifiers provide rail-to-rail output swing with a slew rate of 0.7 V/µs. DAC A and DAC B share a common external reference input, namely V_{REF}-AB. DAC C and DAC D share a common external reference input, namely V_{REF}-CD. Each reference input may be buffered to draw virtually no current from the reference source or unbuffered to give a reference input range from GND to V_{DD}. The devices have a power-down mode in which all DACs may be turned off completely with a high impedance output.

Each DAC output is not updated until it receives the LDAC command. Therefore, while a new value is written to the DAC registers, this value is not represented by a voltage output until the DACs receive the LDAC command. Reading back from any DAC register prior to issuing an LDAC command results in the digital value that corresponds to the DAC output voltage. Therefore, the digital value written to the DAC register cannot be read back until after the LDAC command has been initiated. This LDAC command can be given by either pulling the $\overline{\text{LDAC}}$ pin low (falling edge loads DACs), setting up Bit D4 and Bit D5 of the DAC Configuration register (Address 0x1B), or using the LDAC Configuration register (Address 0x1C).

When using the $\overline{\text{LDAC}}$ pin to control DAC register loading, the low going pulse width should be 20 ns minimum. The $\overline{\text{LDAC}}$ pin has to go high and low again before the DAC registers can be reloaded.

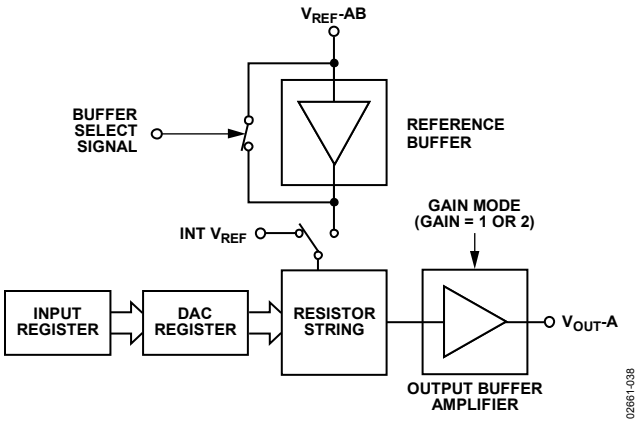

Figure 39. Single DAC Channel Architecture

DIGITAL-TO-ANALOG SECTION

The architecture of a DAC channel consists of a resistor string DAC followed by an output buffer amplifier. The voltage at the V_{REF} pin or the on-chip reference of 2.28 V provides the reference voltage for the corresponding DAC. Figure 39 shows a block diagram of the DAC architecture. Because the input coding to the DAC is straight binary, the ideal output voltage is given by

$$V_{OUT} = \frac{V_{REF} \times D}{2^N}$$

where:

D = the decimal equivalent of the binary code that is loaded to the DAC register:

0 to 255 for ADT7318 (8 bits).
0 to 1023 for ADT7317 (10 bits).
0 to 4095 for ADT7316 (12 bits).

N = the DAC resolution.

RESISTOR STRING

The resistor string section is shown in Figure 40. It is a string of resistors, each approximately 603 Ω. The digital code loaded to the DAC register determines the node on the string where the voltage is tapped off to be fed into the output amplifier. The voltage is tapped off by closing one of the switches connecting the string to the amplifier. Because it is a string of resistors, it is guaranteed monotonic.

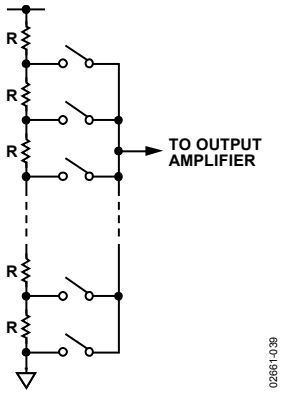

Figure 40. Resistor String

DAC EXTERNAL REFERENCE INPUTS

There is a reference pin for each pair of DACs. The reference inputs are buffered, but can also be individually configured as unbuffered. The advantage with the buffered input is the high impedance it presents to the voltage source driving it. However, if the unbuffered mode is used, the user can have a reference voltage as low as 0.25 V and as high as V_{DD}, because there is no restriction due to headroom and footroom of the reference amplifier. If there is a buffered reference in the circuit, there is no need to use the on-chip buffers. In unbuffered mode, the input impedance is still large at typically 90 kΩ per reference input for 0 V to V_{REF} output mode and 45 kΩ for 0 V to 2 V_{REF} output mode.

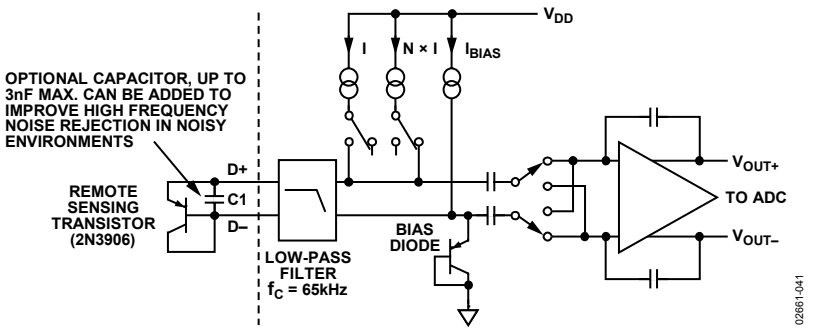

Figure 41. Signal Conditioning for External Diode Temperature Sensors

The buffered/unbuffered option is controlled by the DAC Configuration register (Address 0x1B; see the Registers section). The LDAC Configuration register controls the selection between internal and external voltage references. The default setting is for external reference to be selected.

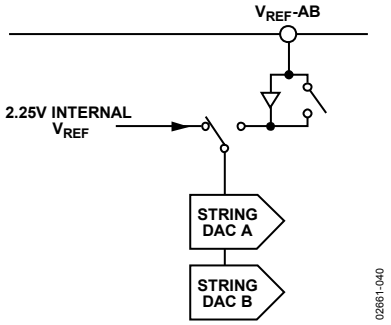

Figure 42. DAC Reference Buffer Circuit

OUTPUT AMPLIFIER

The output buffer amplifier is capable of generating output voltages to within 1 mV of either rail. Its actual range depends on the value of V_{REF}, gain, and offset error.

If a gain of 1 is selected (Bit 0 to Bit 3 = 0, DAC Configuration register, Address 0x1B), the output range is 0.001 V to V_{REF}.

If a gain of 2 is selected (Bit 0 to Bit 3 = 1, DAC Configuration register, Address 0x1B), the output range is 0.001 V to 2 V_{REF}. Because of clamping, however, the maximum output is limited to V_{DD} − 0.001 V.

The output amplifier is capable of driving a load of 4.7 kΩ to V_{DD} or 4.7 kΩ to GND in parallel with 200 pF to GND (see Figure 6). The source and sink capabilities of the output amplifier can be seen in Figure 20.

The slew rate is 0.7 V/μs with a half-scale settling time to ±0.5 LSB (at 8 bits) of 6 μs.

THERMAL VOLTAGE OUTPUT

The ADT7316/ADT7317/ADT7318 are capable of outputting voltages that are proportional to temperature. The DAC A output can be configured to represent the temperature of the internal sensor while DAC B output can be configured to represent the external temperature sensor. Bit C5 and Bit C6 of the Control Configuration 3 register select the temperature proportional to output voltage. Each time a temperature measurement is taken, the DAC output is updated. The output resolution for the ADT7318 is 8 bits with the 1°C change corresponding to the 1 LSB change. The output resolution for the ADT7316 and ADT7317 is capable of 10 bits with a 0.25°C change corresponding to the 1 LSB change.

The default output resolution for the ADT7316 and ADT7317 is 8 bits. To increase this to 10 bits, set C1 = 1 of the Control Configuration 3 register (Address 0x1A). The default output range is 0 V to V_{REF}-AB, and this can be increased to 0 V to 2 V_{REF}-AB. The user can select the internal V_{REF} (V_{REF} = 2.28 V) by setting D4 = 1 in the LDAC Configuration register (Address 0x1C). Increasing the output voltage span to 2 V_{REF} can be done by setting D0 = 1 for DAC A (internal temperature sensor), and D1 = 1 for DAC B (external temperature sensor) in the DAC Configuration register (Address 0x1B).

The output voltage is capable of tracking a maximum temperature range of −128°C to +127°C, but the default setting is −40°C to +127°C. If the output voltage range is 0 V to V_{REF}-AB (V_{REF}-AB = 2.25 V), then this corresponds to 0 V representing −40°C, and 1.48 V representing +127°C. This gives an upper dead band between 1.48 V and V_{REF}-AB.

The internal and external analog temperature offset registers can be used to vary this upper dead band, and consequently, the temperature that 0 V corresponds to. Table 6 and Table 7 give examples of how this is done using a DAC output voltage span of V_{REF} and 2 V_{REF}, respectively. Write in the temperature value, in twos complement format, at which 0 V is to start. For example, if using the DAC A output with 0 V to start at −40°C, program 0xD8 into the internal analog temperature offset register (Address 0x21). This is an 8-bit register, and thus, only has a temperature offset resolution of 1°C for all device models. Use the following formulas to determine the value to program into the offset registers.

Negative Temperatures

Offset Register Code (dec) = *(0 V Temp) + 128*

where D7 of Offset Register Code is set to 1 for negative temperatures.

Example:

$$Offset\ Register\ Code\ (\text{dec}) = (-40) + 128 = 88\text{d} = 0\text{x}58$$

Because a negative temperature is input into the equation, DB7 (MSB) of the Offset Register Code is set to 1. Therefore, 0x58 becomes 0xD8:

$$0x58 + \text{DB7}\ (1) = 0\text{xD8}$$

Positive Temperatures

$$Offset\ Register\ Code\ (\text{dec}) = 0\ \text{V Temp}$$

Example:

$$Offset\ Register\ Code\ (\text{dec}) = 10\text{d} = 0\text{x}0\text{A}$$

The following equation is used to work out the various temperatures for the corresponding 8-bit DAC output:

$$8\text{-}Bit\ Temp = (DAC\ O/P \div 1\ LSB) + (0\ \text{V Temp})$$

For example, if the output is 1.5 V, V_{REF}-AB = 2.25 V, 8-bit DAC has an LSB size = 2.25 V/256 = 8.79×10^{-3}, and 0 V temp is at −128°C, then the resultant temperature is

$$\left(1.5 \div 8.79 \times 10^{-3}\right) + (-128) = +43^{\circ}\text{C}$$

The following equation is used to work out the various temperatures for the corresponding 10-bit DAC output

$$\text{10-Bit Temp} = ((DAC\ O/P \div 1\ LSB) \times 0.25) + (0\ \text{V Temp})$$

For example, if the output is 0.4991 V, V_{REF}-AB = 2.25 V, 10-bit DAC has an LSB size = 2.25 V/1024 = 2.197×10^{-3}, and 0 V temp is at −40°C, then the resulting temperature is

$$\left(\left(0.4991 \div 2.197 \times 10^{-3}\right) \times 0.25\right) + (-40) = 16.75^{\circ}\text{C}$$

Table 6. Thermal Voltage Output (0 V to V_{REF}-AB)

Output Voltage (V)	Default (°C)	Max (°C)	Sample (°C)
0	−40	−128	0
0.5	+17	−71	+56
1	+73	−15	+113
1.12	+87	−1	+127
1.47	+127	+39	UDB[1]
1.5	UDB[1]	+42	UDB[1]
2	UDB[1]	+99	UDB[1]
2.25	UDB[1]	+127	UDB[1]

[1]Upper dead band has been reached. DAC output is not capable of increasing (see Figure 3).

Table 7. Thermal Voltage Output (0 V to 2 V_{REF}-AB)

Output Voltage (V)	Default (°C)	Max (°C)	Sample (°C)
0	−40	−128	0
0.25	−26	−114	+14
0.5	+12	−100	+28
0.75	+3	−85	+43
1	+17	−71	+57
1.12	+23	−65	+63
1.47	+43	−45	+83
1.5	+45	−43	+85
2	+73	−15	+113
2.25	+88	0	+127
2.5	+102	+14	UDB[1]
2.75	+116	+28	UDB[1]
3	UDB[1]	+42	UDB[1]
3.25	UDB[1]	+56	UDB[1]
3.5	UDB[1]	+70	UDB[1]
3.75	UDB[1]	+85	UDB[1]
4	UDB[1]	+99	UDB[1]
4.25	UDB[1]	+113	UDB[1]
4.5	UDB[1]	+127	UDB[1]

[1]Upper dead band has been reached. DAC output is not capable of increasing (see Figure 3).

Figure 43 shows the DAC output vs. temperature for a V_{REF}-AB = 2.25 V.

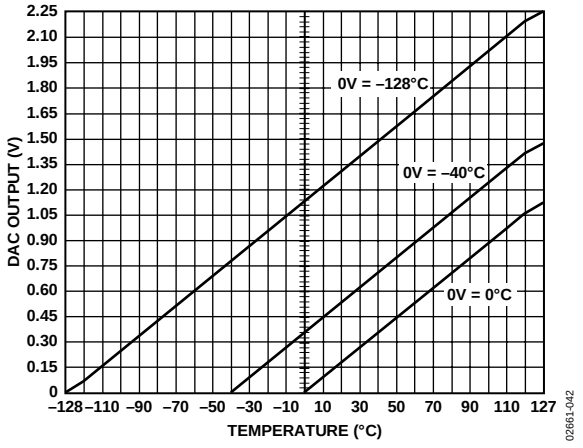

Figure 43. 10-Bit DAC Output vs. Temperature, V_{REF}-AB = 2.25 V

FUNCTIONAL DESCRIPTION—MEASUREMENT

TEMPERATURE SENSOR

The ADT7316/ADT7317/ADT7318 contain an ADC with special input signal conditioning to enable operation with external and on-chip diode temperature sensors. When the ADT7316/ADT7317/ADT7318 are operating in single-channel mode, the ADC continually processes the measurement taken on one channel only. This channel is preselected by Bit C0 and Bit C1 in the Control Configuration 2 register (Address 0x19). When in round robin mode, the analog input multiplexer sequentially selects the V_{DD} input channel, the on-chip temperature sensor to measure its internal temperature, and the external temperature sensor. These signals are digitized by the ADC and the results stored in the various value registers.

The measured results are compared with the internal and external, T_{HIGH} and T_{LOW}, limits. These temperature limits are stored in on-chip registers. If the temperature limits are not masked out, any out-of-limit comparisons generate flags that are stored in the Interrupt Status 1 register (Address 0x00). One or more out-of-limit results cause the INT/$\overline{\text{INT}}$ output to pull either high or low depending on the output polarity setting.

Theoretically, the temperature measuring circuit can measure temperatures from −128°C to +127°C with a resolution of 0.25°C. Temperatures outside T_A, however, are outside the guaranteed operating temperature range of the device. Temperature measurement from −128°C to +127°C is possible using an external sensor.

Temperature measurement is initiated by three methods. The first method is applicable when the part is in single-channel measurement mode. The temperature is measured 16 times and internally averaged to reduce noise. In single-channel mode, the part continuously monitors the selected channel, that is, as soon as one measurement is taken, then another one is started on the same channel. The total time to measure a temperature channel with the ADC operating at slow speed is typically 11.4 ms (712 µs × 16) for the internal temperature sensor, and 24.22 ms (1.51 ms × 16) for the external temperature sensor. The new temperature value is stored in two 8-bit registers and ready for reading by the I^2C or SPI interface. The user can disable the averaging by setting Bit 5 = 1 in the Control Configuration 2 register (Address 0x19). The ADT7316/ADT7317/ADT7318 default on power-up, with the averaging enabled.

The second temperature measurement method is applicable when the part is in round robin measurement mode. The part measures both the internal and external temperature sensors as it cycles through all possible measurement channels. The two temperature channels are measured each time the part runs a round robin sequence. In round-robin mode, the part continuously measures all channels.

The third temperature measurement method is initiated after every read or write to the part when the part is in either single-channel measurement mode or round robin measurement mode. Once serial communication has started, any conversion in progress is stopped and the ADC reset. Conversion starts again immediately after the serial communication has finished. The temperature measurement proceeds normally as described earlier.

V_{DD} MONITORING

The ADT7316/ADT7317/ADT7318 can monitor their own power supplies. The parts measure the voltage on their V_{DD} pin to a resolution of 10 bits. The resulting value is stored in two 8-bit registers: the 2 LSBs are stored in the Internal Temperature Value/V_{DD} Value register (Address 0x03) and the 8 MSBs are stored in the V_{DD} Value Register MSBs register (Address 0x06). This allows the user to perform a 1-byte read if 10-bit resolution is not important. The measured result is compared with V_{HIGH} and V_{LOW} limits. If the V_{DD} interrupt is not masked out, any out-of-limit comparison generates a flag in the Interrupt Status 2 register (Address 0x10), and one or more out-of-limit results cause the INT/$\overline{\text{INT}}$ output to pull either high or low depending on the output polarity setting.

Measuring the voltage on the V_{DD} pin is regarded as monitoring a channel. Therefore, along with the internal and external temperature sensors, the V_{DD} voltage makes up the third and final monitoring channel. The user can select the V_{DD} channel for single-channel measurement by setting Bit C4 = 1 and setting Bit C0 to Bit C2 to all 0s in the Control Configuration 2 register (Address 0x19).

When measuring the V_{DD} value, the reference for the ADC is sourced from the internal reference. Table 8 shows the data format. As the maximum V_{DD} voltage measurable is 7 V, internal scaling is performed on the V_{DD} voltage to match the 2.28 V internal reference value. An example of how the transfer function works follows.

V_{DD} = 5 V

ADC Reference = 2.28 V

1 LSB = *ADC Reference*/2^{10} = 2.28/1024 = 2.226 mV

Scale Factor = *Full-Scale* V_{CC}/*ADC Reference* = 7/2.28 = 3.07

Conversion Result = V_{DD}/(*Scale Factor* × *LSB Size*)

= 5/(3.07 × 2.226 mV)

= 0x2DB

Table 8. V_{DD} Data Format, V_{REF} = 2.28 V

	Digital Output	
V_{DD} Value (V)	**Binary**	**Hex**
2.5	01 0110 1110	16E
3.0	01 1011 0111	1B7
3.5	10 0000 0000	200
4.0	10 0100 1001	249
4.5	10 1001 0010	292
5.0	10 1101 1100	2DC
5.5	11 0010 0101	325
6.0	11 0110 1110	36E
6.5	11 1011 0111	3B7
7.0	11 1111 1111	3FF

ON-CHIP REFERENCE

The ADT7316/ADT7317/ADT7318 have an on-chip 1.2 V band gap reference that is gained up by a switched capacitor amplifier to give an output of 2.28 V. The amplifier is powered up for the duration of the device monitoring phase and is powered down once monitoring is disabled. This saves on current consumption. The internal reference is used as the reference for the ADC. The ADC is used for measuring V_{DD} and the internal and external temperature sensors. The internal reference is always used when measuring V_{DD}, and the internal and external temperature sensors. The external reference is the default power-up reference for the DACs.

ROUND ROBIN MEASUREMENT

On power-up, the ADT7316/ADT7317/ADT7318 go into round robin mode, but monitoring is disabled. Setting Bit C0 of the Configuration 1 Register (Address 0x18) to 1 enables conversions. It sequences through the three channels of V_{DD}, the internal temperature sensor, and the external temperature sensor and takes a measurement from each. Once the conversion is completed on the external temperature sensor, the device loops around for another measurement cycle on all three channels. (This method of taking a measurement on all three channels in one cycle is called round robin.) Setting Bit 4 of the Control Configuration 2 register (Address 0x19) disables the round-robin mode and in turn sets up the single-channel mode. The single-channel mode is where only one channel (for example, the internal temperature sensor) is measured in each conversion cycle.

The time taken to monitor all channels is typically not of interest, because the most recently measured value can be read at any time.

For applications where the round-robin time is important, typical times at 25°C are given in the Specifications section.

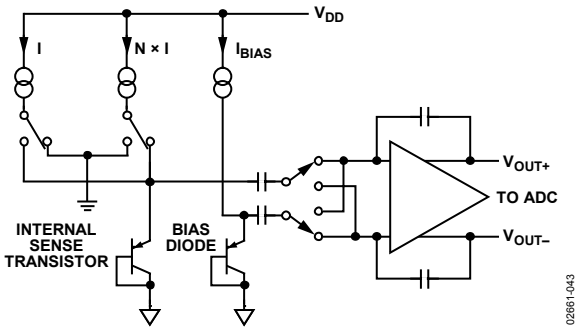

Figure 44. Top Level Structure of Internal Temperature Sensors

SINGLE-CHANNEL MEASUREMENT

Setting C4 of the Control Configuration 2 register (Address 0x19) enables the single-channel mode and allows the ADT7316/ ADT7317/ ADT7318 to focus on one channel only. A channel is selected by writing to Bit C0 and Bit C1 in the Control Configuration 2 register. For example, to select the V_{DD} channel for monitoring, write to the Control Configuration 2 register and set C4 = 1 (if this has not been done), then write all 0s to Bit C0 to Bit C1. All subsequent conversions are done on the V_{DD} channel only. To change the channel selection to the internal temperature channel, write to the Control Configuration 2 register and set C0 = 1. When measuring in single-channel mode, conversions on the channel selected occur directly after each other. Any communication to the ADT7316/ADT7317/ ADT7318 stops the conversions, but they are restarted once the read or write operation is completed.

TEMPERATURE MEASUREMENT METHOD

Internal Temperature Measurement

The ADT7316/ADT7317/ADT7318 contain an on-chip, band gap temperature sensor whose output is digitized by the on-chip ADC. The temperature data is stored in the internal temperature value register. As both positive and negative temperatures can be measured, the temperature data is stored in twos complement format, as shown in Table 9. The thermal characteristics of the measurement sensor can change, and therefore an offset is added to the measured value to enable the transfer function to match the thermal characteristics. This offset is added before the temperature data is stored. The offset value used is stored in the internal temperature offset register.

External Temperature Measurement

The ADT7316/ADT7317/ADT7318 can measure the temperature of one external diode sensor or diode-connected transistor.

The forward voltage of a diode or diode-connected transistor, operated at a constant current, exhibits a negative temperature coefficient of about –2 mV/°C. Unfortunately, the absolute value of V_{BE} varies from device to device, and individual calibration is required to null this out, so the technique is unsuitable for mass production.

The technique used in the ADT7316/ADT7317/ADT7318 is to measure the change in V_{BE} when the device is operated at two different currents. This is given by

$$\Delta V_{BE} = KT/q \times \ln (N)$$

where:
K is Boltzmann's constant.
q is the charge on the carrier.
T is the absolute temperature in Kelvin.
N is the ratio of the two currents.

Figure 41 shows the input signal conditioning used to measure the output of an external temperature sensor. This figure shows the external sensor as a discrete substrate transistor. If a PNP transistor is used, the base is connected to the D− input and the emitter to the D+ input. If an NPN transistor is used, the emitter is connected to the D− input and the base to the D+ input.

A 2N3906 is recommended to be used as the external transistor.

To prevent ground noise interfering with the measurement, the more negative terminal of the sensor is not referenced to ground, but is biased above ground by an internal diode at the D− input. As the sensor is operating in a noisy environment, C1 is provided as a noise filter. See the Layout Considerations section on for more information on C1.

To measure ΔV_{BE}, the sensor is switched between operating currents of I and N × I. The resulting waveform is passed through a low-pass filter to remove noise, then to a chopper stabilized amplifier that performs the functions of amplification and rectification of the waveform to produce a dc voltage proportional to ΔV_{BE}. This voltage is measured by the ADC to give a temperature output in 10-bit twos complement format. To further reduce the effects of noise, digital filtering is performed by averaging the results of 16 measurement cycles.

TEMPERATURE VALUE FORMAT

One LSB of the ADC corresponds to 0.25°C. The ADC can theoretically measure a temperature span of 255°C. The internal temperature sensor is guaranteed to a low value limit of −40°C. It is possible to measure the full temperature span using the external temperature sensor. The temperature data format is shown in Table 9. The result of the internal or external temperature measurements is stored in the temperature value registers and is compared with limits programmed into the internal or external high and low registers.

Table 9. Temperature Data Format (Internal and External Temperature)

Temperature	Digital Output DB9.....DB0
−40°C	11 0110 0000
−25°C	11 1001 1100
−10°C	11 1101 1000
−0.25°C	11 1111 1111
0°C	00 0000 0000
0.25°C	00 0000 0001
10°C	00 0010 1000
25°C	00 0110 0100
50°C	00 1100 1000
75°C	01 0010 1100
100°C	01 1001 0000
105°C	01 1010 0100
125°C	01 1111 0100

Temperature Conversion Formula

Positive Temperature = ADC Code/4

Negative Temperature = (ADC Code − 512)/4

where DB9 is removed from the ADC code in the Negative Temperature equation.

INTERRUPTS

The measured results from the internal temperature sensor, external temperature sensor, and the V_{DD} pin are compared with the T_{HIGH}/V_{HIGH} (greater than comparison) and T_{LOW}/V_{LOW} (less than or equal to comparison) limits. An interrupt occurs if the measurement exceeds or equals the limit registers. These limits are stored in on-chip registers. Note that the limit registers are 8 bits long, while the conversion results are 10 bits long. If the limits are not masked out, then any out-of-limit comparisons generate flags that are stored in the Interrupt Status 1 register (Address 0x00) and the Interrupt Status 2 register (Address 0x01). One or more out-of-limit results cause the INT/$\overline{\text{INT}}$ output to pull either high or low depending on the output polarity setting. It is good design practice to mask out interrupts for channels that are of no concern to the application.

Figure 45 shows the interrupt structure for the ADT7316/ADT7317/ADT7318. It shows a block diagram of how the various measurement channels affect the INT/$\overline{\text{INT}}$ pin.

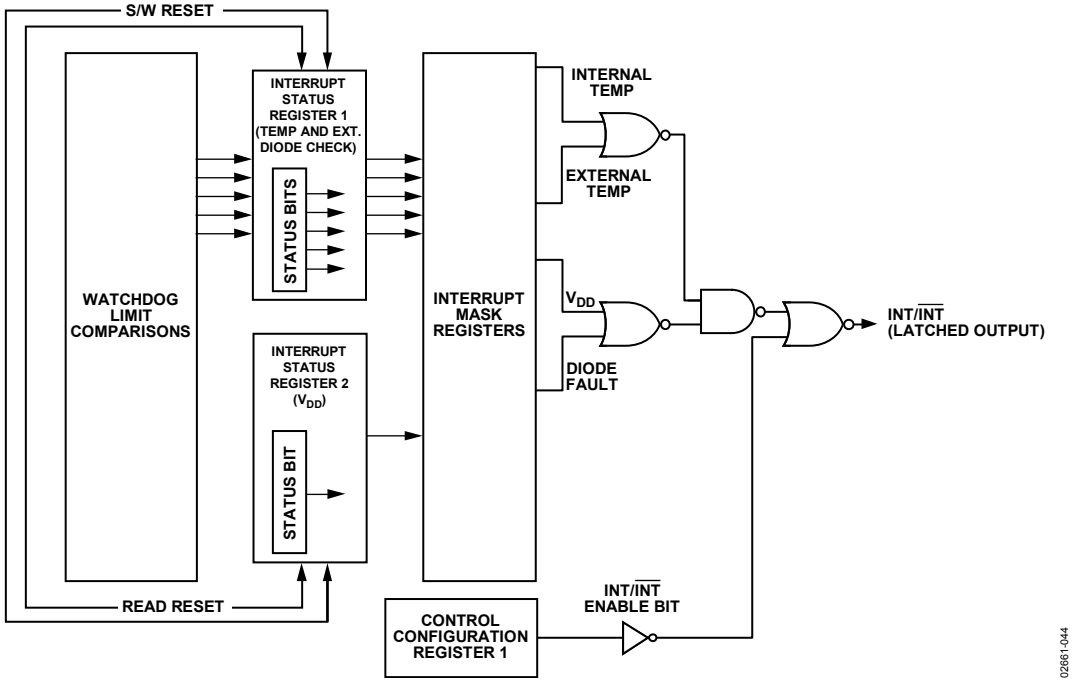

Figure 45. ADT7316/ADT7317/ADT7318 Interrupt Structure

REGISTERS

The ADT7316/ADT7317/ADT7318 contain registers that are used to store the results of external and internal temperature measurements, V_{DD} value measurements, high and low temperature and supply voltage limits. They also set output DAC voltage levels, configure multipurpose pins, and generally control the device. A description of these registers follows.

The register map is divided into registers of 8 bits. Each register has its own individual address, but some consist of data that is linked with other registers. These registers hold the 10-bit conversion results of measurements taken on the temperature and V_{DD} channels. For example, the 8 MSBs of the V_{DD} measurement are stored in V_{DD} Value Register MSBs Register (Address 0x06), while the 2 LSBs are stored in Internal Temperature Value/V_{DD} Value LSBs Register Address 0x03. These types of registers are linked in that when the LSB register is read first, the MSB registers associated with that LSB register are locked out to prevent any updates. To unlock these MSB registers, the user has only to read any one of them, which effectively unlocks all previously locked-out MSB registers. Therefore, for the example given earlier, if Register 0x03 is read first, MSB Register 0x06 and Register 0x07 are locked out to prevent any updates to them. If Register 0x06 is read, then this register and Register 0x07 would be subsequently unlocked.

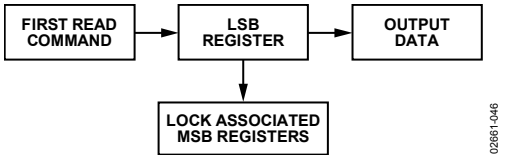

Figure 46. Phase 1 of 10-Bit Read

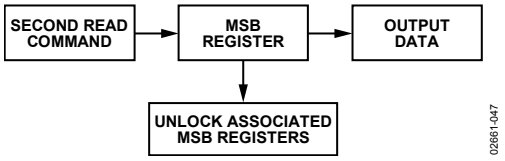

Figure 47. Phase 2 of 10-Bit Read

If an MSB register is read first, its corresponding LSB register is not locked out, allowing the user to read back only 8 bits (MSB) of a 10-bit conversion result. Reading an MSB register first does not lock out other MSB registers, and likewise, reading an LSB register first does not lock out other LSB registers.

Table 10. List of ADT7316/ADT7317/ADT7318 Registers

RD/WR Address	Name	Power-On Default
0x00	Interrupt Status 1	0x00
0x01	Interrupt Status 2	0x00
0x02	Reserved	0x00
0x03	Internal Temp and V_{DD} LSBs	0x00
0x04	External Temp LSBs	0x00
0x05	Reserved	0x00
0x06	V_{DD} MSBs	0xxx
0x07	Internal Temp MSBs	0x00
0x08	External Temp MSBs	0x00
0x09 to 0x0F	Reserved	0x00
0x10	DAC A LSBs (ADT7316/ADT7317 only)	0x00
0x11	DAC A MSBs	0x00
0x12	DAC B LSBs (ADT7316/ADT7317 only)	0x00
0x13	DAC B MSBs	0x00
0x14	DAC C LSBs (ADT7316/ADT7317 only)	0x00
0x15	DAC C MSBs	0x00
0x16	DAC D LSBs (ADT7316/ADT7317 only)	0x00
0x17	DAC D MSBs	0x00
0x18	Control Configuration 1	0x00
0x19	Control Configuration 2	0x00
0x1A	Control Configuration 3	0x00
0x1B	DAC Configuration	0x00
0x1C	LDAC Configuration	0x00
0x1D	Interrupt Mask 1	0x00
0x1E	Interrupt Mask 2	0x00
0x1F	Internal Temp Offset	0x00
0x20	External Temp Offset	0x00
0x21	Internal Analog Temp Offset	0xD8
0x22	External Analog Temp Offset	0xD8
0x23	V_{DD} V_{HIGH} Limit	0xC7
0x24	V_{DD} V_{LOW} Limit	0x62
0x25	Internal T_{HIGH} Limit	0x64
0x26	Internal T_{LOW} Limit	0xC9
0x27	External T_{HIGH} Limit	0xFF
0x28	External T_{LOW} Limit	0x00
0x29 to 0x4C	Reserved	
0x4D	Device ID	0x01/0x09/0x05
0x4E	Manufacturer's ID	0x41
0x4F	Silicon Revision	0xXx
0x50 to 0x7E	Reserved	0x00
0x7F	SPI Lock Status	0x00
0x80 to 0xFF	Reserved	0x00

REGISTER DESCRIPTIONS

The bit maps in this section show the register default settings at power-up, unless otherwise noted.

Interrupt Status 1 Register (Read-Only) [Address 0x00]
This 8-bit, read-only register reflects the status of some of the interrupts that can cause the INT/$\overline{\text{INT}}$ pin to go active. This register is reset by a read operation, provided that any out-of-limit event has been corrected. It is also reset by a software reset.

Table 11. Interrupt Status 1 Register

D7	D6	D5	D4	D3	D2	D1	D0
N/A	N/A	N/A	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

Table 12. Interrupt Status 1 Register

Bit	Function
D0	1 when internal temperature value exceeds T_{HIGH} limit. Any internal temperature reading greater than the limit set causes an out-of-limit event.
D1	1 when internal temperature value exceeds T_{LOW} limit. Any internal temperature reading less than or equal to the limit set causes an out-of-limit event.
D2	1 when external temperature value exceeds T_{HIGH} limit. The default value for this limit register is –1°C, so any external temperature reading greater than the limit set causes an out-of-limit event.
D3	1 when external temperature value exceeds T_{LOW} limit. The default value for this limit register is 0°C, so any external temperature reading less than or equal to the limit set causes an out-of-limit event.
D4	1 indicates a fault (open or short) for the external temperature sensor.

Interrupt Status 2 Register (Read-Only) [Address 0x01]
This 8-bit, read-only register reflects the status of the V_{DD} interrupt that can cause the INT/$\overline{\text{INT}}$ pin to go active. This register is reset by a read operation, provided that any out-of-limit event has been corrected. It is also reset by a software reset.

Table 13. Interrupt Status 2 Register

D7	D6	D5	D4	D3	D2	D1	D0
N/A	N/A	N/A	0[1]	N/A	N/A	N/A	N/A

[1] Default settings at power-up.

Table 14. Interrupt Status 2 Register Bit Descriptions

Bit	Function
D4	1 when V_{DD} value is greater than the corresponding V_{HIGH} limit. 1 when V_{DD} is less than or equal to the corresponding V_{LOW} limit.

Internal Temperature Value/V_{DD} Value Register LSBs (Read-Only) [Address 0x03]
This 8-bit, read-only register stores the 2 LSBs of the 10-bit temperature reading from the internal temperature sensor and the 2 LSBs of the 10-bit supply voltage reading.

Table 15. Internal Temperature/V_{DD} LSBs

D7	D6	D5	D4	D3	D2	D1	D0
N/A	N/A	N/A	N/A	V1	LSB	T1	LSB
N/A	N/A	N/A	N/A	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

Table 16. Internal Temperature/V_{DD} LSBs Bit Descriptions

Bit	Function
D0	LSB of internal temperature value.
D1	B1 of internal temperature value.
D2	LSB of V_{DD} value.
D3	B1 of V_{DD} value.

External Temperature Value Register LSBs (Read-Only) [Address 0x04]
This 8-bit, read-only register stores the 2 LSBs of the 10-bit temperature reading from the external temperature sensor.

Table 17. External Temperature LSBs

D7	D6	D5	D4	D3	D2	D1	D0
N/A	N/A	N/A	N/A	N/A	N/A	T1	LSB
N/A	N/A	N/A	N/A	N/A	N/A	0[1]	0[1]

[1] Default settings at power-up.

Table 18. External Temperature LSBs Bit Descriptions

Bit	Function
D0	LSB of external temperature value.
D1	B1 of external temperature value.

V_{DD} Value Register MSBs (Read-Only) [Address 0x06]
This 8-bit, read-only register stores the supply voltage value. The 8 MSBs of the 10-bit value are stored in this register.

Table 19. V_{DD} Value MSBs

D7	D6	D5	D4	D3	D2	D1	D0
V9	V8	V7	V6	V5	V4	V3	V2
X[1]	X[1]	X[1]	X[1]	X[1]	X[1]	X[1]	X[1]

[1] Loaded with V_{DD} value after power-up.

Internal Temperature Value Register MSBs (Read-Only) [Address 0x07]
This 8-bit, read-only register stores the internal temperature value from the internal temperature sensor in twos complement format. The 8 MSBs of the 10-bit value are stored in this register.

Table 20. Internal Temperature Value MSBs

D7	D6	D5	D4	D3	D2	D1	D0
T9	T8	T7	T6	T5	T4	T3	T2
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

External Temperature Value Register MSBs (Read-Only) [Address 0x08]

This 8-bit, read-only register stores the external temperature value from the external temperature sensor in twos complement format. The 8 MSBs of the 10-bit value are stored in this register.

Table 21. External Temperature Value MSBs

D7	D6	D5	D4	D3	D2	D1	D0
T9	T8	T7	T6	T5	T4	T3	T2
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

DAC A Register LSBs (Read/Write) [Address 0x10]

This 8-bit read/write register contains the 4/2 LSBs of the ADT7316/ADT7317 DAC A word, respectively. The value in this register is combined with the value in the DAC A Register MSBs and converted to an analog voltage on the V_{OUT}-A pin. On power-up, the voltage output on the V_{OUT}-A pin is 0 V.

Table 22. DAC A (ADT7316) LSBs

D7	D6	D5	D4	D3	D2	D1	D0
B3	B2	B1	LSB	N/A	N/A	N/A	N/A
0[1]	0[1]	0[1]	0[1]	N/A	N/A	N/A	N/A

[1] Default settings at power-up.

Table 23. DAC A (ADT7317) LSBs

D7	D6	D5	D4	D3	D2	D1	D0
B1	LSB	N/A	N/A	N/A	N/A	N/A	N/A
0[1]	0[1]	N/A	N/A	N/A	N/A	N/A	N/A

[1] Default settings at power-up.

DAC A Register MSBs (Read/Write) [Address 0x11]

This 8-bit read/write register contains the 8 MSBs of the DAC A word. The value in this register is combined with the value in the DAC A Register LSBs and converted to an analog voltage on the V_{OUT}-A pin. On power-up, the voltage output on the V_{OUT}-A pin is 0 V.

Table 24. DAC A MSBs

D7	D6	D5	D4	D3	D2	D1	D0
MSB	B8	B7	B6	B5	B4	B3	B2
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

DAC B Register LSBs (Read/Write) [Address 0x12]

This 8-bit read/write register contains the 4/2 LSBs of the ADT7316/ADT7317 DAC B word, respectively. The value in this register is combined with the value in the DAC B register MSBs and converted to an analog voltage on the V_{OUT}-B pin. On power-up, the voltage output on the V_{OUT}-B pin is 0 V.

Table 25. DAC B (ADT7316) LSBs

D7	D6	D5	D4	D3	D2	D1	D0
B3	B2	B1	LSB	N/A	N/A	N/A	N/A
0[1]	0[1]	0[1]	0[1]	N/A	N/A	N/A	N/A

[1] Default settings at power-up.

Table 26. DAC B (ADT7317) LSBs

D7	D6	D5	D4	D3	D2	D1	D0
B1	LSB	N/A	N/A	N/A	N/A	N/A	N/A
0[1]	0[1]	N/A	N/A	N/A	N/A	N/A	N/A

[1] Default settings at power-up.

DAC B Register MSBs (Read/Write) [Address 0x13]

This 8-bit read/write register contains the 8 MSBs of the DAC B word. The value in this register is combined with the value in the DAC B register LSBs and converted to an analog voltage on the V_{OUT}-B pin. On power-up, the voltage output on the V_{OUT}-B pin is 0 V.

Table 27. DAC B MSBs

D7	D6	D5	D4	D3	D2	D1	D0
MSB	B8	B7	B6	B5	B4	B3	B2
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

DAC C Register LSBs (Read/Write) [Address 0x14]

This 8-bit read/write register contains the 4/2 LSBs of the ADT7316/ADT7317 DAC C word, respectively. The value in this register is combined with the value in the DAC C register MSBs and converted to an analog voltage on the V_{OUT}-C pin. On power-up, the voltage output on the V_{OUT}-C pin is 0 V.

Table 28. DAC C (ADT7316) LSBs

D7	D6	D5	D4	D3	D2	D1	D0
B3	B2	B1	LSB	N/A	N/A	N/A	N/A
0[1]	0[1]	0[1]	0[1]	N/A	N/A	N/A	N/A

[1] Default settings at power-up.

Table 29. DAC C (ADT7317) LSBs

D7	D6	D5	D4	D3	D2	D1	D0
B1	LSB	N/A	N/A	N/A	N/A	N/A	N/A
0[1]	0[1]	N/A	N/A	N/A	N/A	N/A	N/A

[1] Default settings at power-up.

DAC C Register MSBs (Read/Write) [Address 0x15]

This 8-bit read/write register contains the 8 MSBs of the DAC C word. The value in this register is combined with the value in the DAC C register LSBs and converted to an analog voltage on the V_{OUT}-C pin. On power-up, the voltage output on the V_{OUT}-C pin is 0 V.

Table 30. DAC C MSBs

D7	D6	D5	D4	D3	D2	D1	D0
MSB	B8	B7	B6	B5	B4	B3	B2
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

DAC D Register LSBs (Read/Write) [Address 0x16]
This 8-bit read/write register contains the 4/2 LSBs of the ADT7316/ADT7317 DAC D word, respectively. The value in this register is combined with the value in the DAC D register MSBs and converted to an analog voltage on the V_{OUT}-D pin. On power-up, the voltage output on the V_{OUT}-D pin is 0 V.

Table 31. DAC D (ADT7316) LSBs

D7	D6	D5	D4	D3	D2	D1	D0
B3	B2	B1	LSB	N/A	N/A	N/A	N/A
0[1]	0[1]	0[1]	0[1]	N/A	N/A	N/A	N/A

[1] Default settings at power-up.

Table 32. DAC D (ADT7317) LSBs

D7	D6	D5	D4	D3	D2	D1	D0
B1	LSB	N/A	N/A	N/A	N/A	N/A	N/A
0[1]	0[1]	N/A	N/A	N/A	N/A	N/A	N/A

[1] Default settings at power-up.

DAC D Register MSBs (Read/Write) [Address 0x17]
This 8-bit read/write register contains the 8 MSBs of the DAC D word. The value in this register is combined with the value in the DAC D register LSBs and converted to an analog voltage on the V_{OUT}-D pin. On power-up, the voltage output on the V_{OUT}-D pin is 0 V.

Table 33. DAC D MSBs

D7	D6	D5	D4	D3	D2	D1	D0
MSB	B8	B7	B6	B5	B4	B3	B2
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

Control Configuration 1 Register (Read/Write) [Address 0x18]
This configuration register is an 8-bit read/write register that is used to setup some of the operating modes of the ADT7316/ ADT7317/ADT7318.

Table 34. Control Configuration 1

D7	D6	D5	D4	D3	D2	D1	D0
PD	C6	C5	C4	C3	C2	C1	C0
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

Table 35. Control Configuration 1 Bit Descriptions

Bit	Function
C0	This bit enables/disables conversions in round robin mode and single-channel mode. The ADT7316/ADT7317/ ADT7318 power up in round-robin mode, but monitoring is not initiated until this bit is set. 0 = Stop monitoring (default). 1 = Start monitoring.
C1:4	Reserved. Only write 0s.
C5	0 = Enable INT/$\overline{INT}$ output. 1 = Disable INT/$\overline{INT}$ output.
C6	Configures INT/$\overline{INT}$ output polarity. 0 = Active low. 1 = Active high.
PD	Power-Down Bit. Setting this bit to 1 puts the ADT7316/ ADT7317/ADT7318 into standby mode. In this mode, both the ADC and the DACs are fully powered down, but the serial interface is still operational. To power up the part again, write 0 to this bit.

Control Configuration 2 Register (Read/Write) [Address 0x19]
This configuration register is an 8-bit, read/write register that is used to set up some of the operating modes of the ADT7316/ ADT7317/ADT7318.

Table 36. Control Configuration 2

D7	D6	D5	D4	D3	D2	D1	D0
C7	C6	C5	C4	C3	C2	C1	C0
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

Table 37. Control Configuration 2

Bit	Function
C0:1	In single-channel mode, these bits select between V_{DD}, the internal temperature sensor, and the external temperature sensor for conversion. 00 = V_{DD} (default). 01 = Internal temperature sensor. 10 = External temperature sensor. 11 = Reserved.
C2:3	Reserved.
C4	Selects between single-channel and round robin conversion cycle. Default is round robin. 0 = Round robin. 1 = Single channel.
C5	Default condition is to average every measurement on all channels 16 times. This bit disables this averaging. Channels affected are temperature and V_{DD}. 0 = Enable averaging. 1 = Disable averaging.
C6	SMBus timeout on the serial clock puts a 25 ms limit on the pulse width of the clock. Ensures that a fault on the master SCL does not lock up the SDA line. SMBus timeout. 0 = Disable. 1 = Enable SMBus timeout.
C7	Software reset. Setting this bit to 1 causes a software reset. All registers and DAC outputs reset to their default settings.

Control Configuration 3 Register (Read/Write) [Address 0x1A]

This configuration register is an 8-bit read/write register that is used to set up some of the operating modes of the ADT7316/ADT7317/ADT7318.

Table 38. Control Configuration 3

D7	D6	D5	D4	D3	D2	D1	D0
C7	C6	C5	C4	C3	C2	C1	C0
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

Table 39. Control Configuration 3

Bit	Function
C0	Selects between fast and normal ADC conversion speeds for all three monitoring channels. 0 = ADC clock at 1.4 kHz. 1 = ADC clock at 22.5 kHz. D+ and D− analog filters are disabled.
C1	On the ADT7316 and ADT7317, this bit selects between 8-bit and 10-bit DAC output resolution on the thermal voltage output feature. Default = 8 bits. This bit has no effect on the ADT7318 output because this part has only an 8-bit DAC. In the ADT7318 case, write 0 to this bit. 0 = 8-bit resolution. 1 = 10-bit resolution.
C2	Reserved. Only write 0.
C3	0 = $\overline{\text{LDAC}}$ pin controls updating of DAC outputs. 1 = DAC configuration register and LDAC configuration register control the updating of the DAC outputs.
C4	Reserved. Only write 0.
C5	Setting this bit selects DAC A voltage output to be proportional to the internal temperature measurement.
C6	Setting this bit selects DAC B voltage output to be proportional to the external temperature measurement.
C7	Reserved. Only write 0.

DAC Configuration Register (Read/Write) [Address 0x1B]

This configuration register is an 8-bit, read/write register that is used to control the output ranges of all four DACs and to control the loading of the DAC registers if the $\overline{\text{LDAC}}$ pin is disabled (Bit C3 = 1, Control Configuration 3 register).

Table 40. DAC Configuration

D7	D6	D5	D4	D3	D2	D1	D0
D7	D6	D5	D4	D3	D2	D1	D0
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

Table 41. DAC Configuration

Bit	Function
D0	Selects the output range of DAC A. 0 = 0 V to V_{REF}. 1 = 0 V to 2 V_{REF}.
D1	Selects the output range of DAC B. 0 = 0 V to V_{REF}. 1 = 0 V to 2 V_{REF}.
D2	Selects the output range of DAC C. 0 = 0 V to V_{REF}. 1 = 0 V to 2 V_{REF}.
D3	Selects the output range of DAC D. 0 = 0 V to V_{REF}. 1 = 0 V to 2 V_{REF}.
D4:5	00 = MSB write to any DAC register generates an LDAC command, which updates that DAC only. 01 = MSB write to DAC B or DAC D register generates an LDAC command, which updates DAC A, DAC B or DAC C, DAC D, respectively. 10 = MSB write to DAC D register generates an LDAC command, which updates all 4 DACs. 11 = LDAC command generated from LDAC register.
D6	Setting this bit allows the external V_{REF} to bypass the reference buffer when supplying DAC A and DAC B.
D7	Setting this bit allows the external V_{REF} to bypass the reference buffer when supplying DAC C and DAC D.

LDAC Configuration Register (Write-Only) [Address 0x1C]

This configuration register is an 8-bit write register that is used to control the updating of the quad DAC outputs if the $\overline{\text{LDAC}}$ pin is disabled and Bit D4 and Bit D5 of the DAC Configuration register are both set to 1. It also selects either the internal or external V_{REF} for all four DACs. Bit D0 to Bit D3 in this register are self-clearing, that is, reading back from this register always gives 0s for these bits.

Table 42. LDAC Configuration

D7	D6	D5	D4	D3	D2	D1	D0
D7	D6	D5	D4	D3	D2	D1	D0
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

Table 43. LDAC Configuration

Bit	Function
D0	Writing 1 to this bit generates the LDAC command to update the DAC A output only.
D1	Writing 1 to this bit generates the LDAC command to update the DAC B output only.
D2	Writing 1 to this bit generates the LDAC command to update the DAC C output only.
D3	Writing 1 to this bit generates the LDAC command to update the DAC D output only.
D4	Selects either internal V_{REF} or external V_{REF}-AB for DAC A, DAC B, DAC C and DAC D. 0 = External V_{REF}. 1 = Internal V_{REF}.
D5:D7	Reserved. Only write 0s.

Interrupt Mask 1 Register (Read/Write) [Address 0x1D]
This mask register is an 8-bit, read/write register that can be used to mask out any interrupts that can cause the INT/$\overline{INT}$ pin to go active.

Table 44. Interrupt Mask 1

D7	D6	D5	D4	D3	D2	D1	D0
D7	D6	D5	D4	D3	D2	D1	D0
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

Table 45. Interrupt Mask 1 Bit Descriptions

Bit	Function
D0	0 = Enable internal T_{HIGH} interrupt. 1 = Disable internal T_{HIGH} interrupt.
D1	0 = Enable internal T_{LOW} interrupt. 1 = Disable internal T_{LOW} interrupt.
D2	0 = Enable external T_{HIGH} interrupt. 1 = Disable external T_{HIGH} interrupt.
D3	0 = Enable external T_{LOW} interrupt. 1 = Disable external T_{LOW} interrupt.
D4	0 = Enable external temperature fault interrupt. 1 = Disable external temperature fault interrupt.
D5: 7	Reserved. Only write 0s.

Interrupt Mask 2 Register (Read/Write) [Address 0x1E]
This mask register is an 8-bit read/write register that can be used to mask out any interrupts that can cause the INT/$\overline{INT}$ pin to go active.

Table 46. Interrupt Mask 2

D7	D6	D5	D4	D3	D2	D1	D0
D7	D6	D5	D4	D3	D2	D1	D0
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

Table 47. Interrupt Mask 2 Bit Descriptions

Bit	Function
D0:D3	Reserved. Only write 0s.
D4	0 = Enable V_{DD} interrupts. 1 = Disable V_{DD} interrupts.
D5:7	Reserved. Only write 0s.

Internal Temperature Offset Register (Read/Write) [Address 0x1F]
This register contains the offset value for the internal temperature channel. A twos complement number can be written to this register which is then added to the measured result before it is stored or compared to limits. In this way, a one-point calibration can be done whereby the whole transfer function of the channel can be moved up or down. From a software point of view, this may be a very simple method to vary the characteristics of the measurement channel if the thermal characteristics change. As it is an 8-bit register, the temperature resolution is 1°C.

Table 48. Internal Temperature Offset

D7	D6	D5	D4	D3	D2	D1	D0
D7	D6	D5	D4	D3	D2	D1	D0
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

External Temperature Offset Register (Read/Write) [Address 0x20]
This register contains the offset value for the external temperature channel. A twos complement number can be written to this register which is then added to the measured result before it is stored or compared to limits. In this way, one-point calibration can be done whereby the whole transfer function of the channel can be moved up or down. From a software point of view, this may be a very simple method to vary the characteristics of the measurement channel if the thermal characteristics change. As it is an 8-bit register, the temperature resolution is 1°C.

Table 49. External Temperature Offset

D7	D6	D5	D4	D3	D2	D1	D0
D7	D6	D5	D4	D3	D2	D1	D0
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

Internal Analog Temperature Offset Register (Read/Write) [Address 0x21]
This register contains the offset value for the internal thermal voltage output. A twos complement number can be written to this register which is then added to the measured result before it is converted by DAC A. Varying the value in this register has the effect of varying the temperature span. For example, the output voltage can represent a temperature span of −128°C to +127°C or even 0°C to 127°C. In essence, this register changes the position of 0 V on the temperature scale. Anything other than −128°C to +127°C produces an upper dead band on the DAC A output. As it is an 8-bit register, the temperature resolution is 1°C. The default value is −40°C.

Table 50. Internal Analog Temperature Offset

D7	D6	D5	D4	D3	D2	D1	D0
D7	D6	D5	D4	D3	D2	D1	D0
1[1]	1[1]	0[1]	1[1]	1[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

External Analog Temperature Offset Register (Read/Write) [Address 0x22]

This register contains the offset value for the external thermal voltage output. A twos complement number can be written to this register which is then added to the measured result before it is converted by DAC B. Varying the value in this register has the affect of varying the temperature span. For example, the output voltage can represent a temperature span of −128°C to +127°C or even 0°C to 127°C. In essence, this register changes the position of 0 V on the temperature scale. Anything other than −128°C to +127°C produces an upper dead band on the DAC B output. As it is an 8-bit register, the temperature resolution is 1°C. The default value is −40°C.

Table 51. External Analog Temperature

D7	D6	D5	D4	D3	D2	D1	D0
D7	D6	D5	D4	D3	D2	D1	D0
1[1]	1[1]	0[1]	1[1]	1[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

V_{DD} V_{HIGH} Limit Register (Read/Write) [Address 0x23]

This limit register is an 8-bit read/write register that stores the V_{DD} upper limit that causes an interrupt and activates the INT/$\overline{INT}$ output (if enabled). For this to happen, the measured V_{DD} value has to be greater than the value in this register. The default value is 5.46 V.

Table 52. V_{DD} V_{HIGH} Limit

D7	D6	D5	D4	D3	D2	D1	D0
D7	D6	D5	D4	D3	D2	D1	D0
1[1]	1[1]	0[1]	0[1]	0[1]	1[1]	1[1]	1[1]

[1] Default settings at power-up.

V_{DD} V_{LOW} Limit Register (Read/Write) [Address 0x24]

This limit register is an 8-bit read/write register that stores the V_{DD} lower limit that causes an interrupt and activates the INT/$\overline{INT}$ output (if enabled). For this to happen, the measured V_{DD} value has to be less than or equal to the value in this register. The default value is 2.7 V.

Table 53. V_{DD} V_{LOW} Limit

D7	D6	D5	D4	D3	D2	D1	D0
D7	D6	D5	D4	D3	D2	D1	D0
0[1]	1[1]	1[1]	0[1]	0[1]	0[1]	1[1]	0[1]

[1] Default settings at power-up.

Internal T_{HIGH} Limit Register (Read/Write) [Address 0x25]

This limit register is an 8-bit read/write register that stores the twos complement of the internal temperature upper limit that causes an interrupt and activates the INT/$\overline{INT}$ output (if enabled). For this to happen, the measured internal temperature value has to be greater than the value in this register. As it is an 8-bit register, the temperature resolution is 1°C. The default value is 100°C.

Positive Temperature = Limit Register Code (dec)
Negative Temperature = Limit Register Code (dec) – 256

Table 54. Internal T_{HIGH} Limit

D7	D6	D5	D4	D3	D2	D1	D0
D7	D6	D5	D4	D3	D2	D1	D0
0[1]	1[1]	1[1]	0[1]	0[1]	1[1]	0[1]	0[1]

[1] Default settings at power-up.

Internal T_{LOW} Limit Register (Read/Write) [Address 0x26]

This limit register is an 8-bit, read/write register that stores the twos complement of the internal temperature lower limit that causes an interrupt and activates the INT/$\overline{INT}$ output (if enabled). For this to happen, the measured internal temperature value has to be more negative than or equal to the value in this register. As it is an 8-bit register, the temperature resolution is 1°C. The default value is −55°C.

Positive Temperature = Limit Register Code (dec)
Negative Temperature = Limit Register Code (dec) – 256

Table 55. Internal T_{LOW} Limit

D7	D6	D5	D4	D3	D2	D1	D0
D7	D6	D5	D4	D3	D2	D1	D0
1[1]	1[1]	0[1]	0[1]	1[1]	0[1]	0[1]	1[1]

[1] Default settings at power-up.

External T_{HIGH} Limit Register (Read/Write) [Address 0x27]

This limit register is an 8-bit, read/write register that stores the twos complement of the external temperature upper limit that causes an interrupt and activates the INT/$\overline{INT}$ output (if enabled). For this to happen, the measured external temperature value has to be greater than the value in this register. As it is an 8-bit register, the temperature resolution is 1°C. The default value is −1°C.

Positive Temperature = Limit Register Code (dec)
Negative Temperature = Limit Register Code (dec) – 256

Table 56. External T_{HIGH} Limit

D7	D6	D5	D4	D3	D2	D1	D0
D7	D6	D5	D4	D3	D2	D1	D0
1[1]	1[1]	1[1]	1[1]	1[1]	1[1]	1[1]	1[1]

[1] Default settings at power-up.

External T_{LOW} Limit Register (Read/Write) [Address 0x28]
This limit register is an 8-bit, read/write register that stores the twos complement of the external temperature lower limit that causes an interrupt and activates the INT/$\overline{INT}$ output (if enabled). For this to happen, the measured external temperature value has to be more negative than or equal to the value in this register. As it is an 8-bit register, the temperature resolution is 1°C. The default value is 0°C.

Positive Temperature = Limit Register Code (dec)
Negative Temperature = Limit Register Code (dec) – 256

Table 57. External T_{LOW} Limit

D7	D6	D5	D4	D3	D2	D1	D0
D7	D6	D5	D4	D3	D2	D1	D0
0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]	0[1]

[1] Default settings at power-up.

Device ID Register (Read-Only) [Address 0x4D]
This 8-bit, read-only register indicates which part the device is in the model range. ADT7316 = 0x01, ADT7317 = 0x09, and ADT7318 = 0x05.

Manufacturer's ID Register (Read-Only) [Address 0x4E]
This register contains the manufacturers identification number. Analog Devices, Inc.'s ID is 0x41.

Silicon Revision Register (Read-Only) [Address 0x4F]
This register is divided into the 4 LSBs representing the stepping and the 4 MSBs representing the version. The stepping contains the manufacturer's code for minor revisions or steppings to the silicon. The version is the ADT7316/ADT7317/ ADT7318 version number.

SPI Lock Status Register (Read-Only) [Address 0x7F]
Bit D0 (LSB) of this read-only register indicates whether the SPI interface is locked. Writing to this register causes the device to malfunction. The default value is 0x00.

0 = I^2C interface.
1 = SPI interface selected and locked.

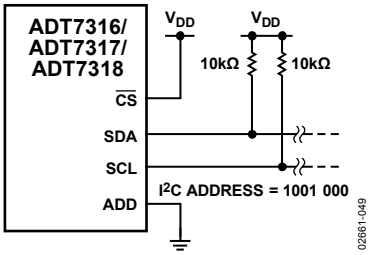

Figure 48. Typical I^2C Interface Connection

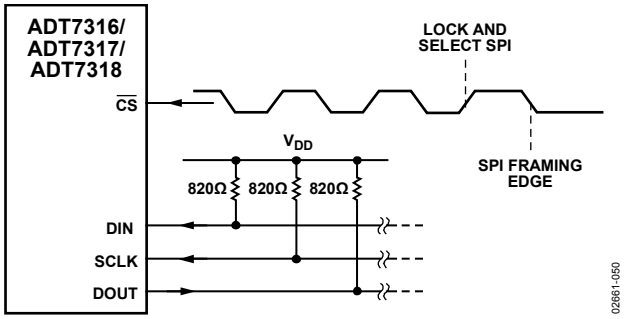

Figure 49. Typical SPI Interface Connection

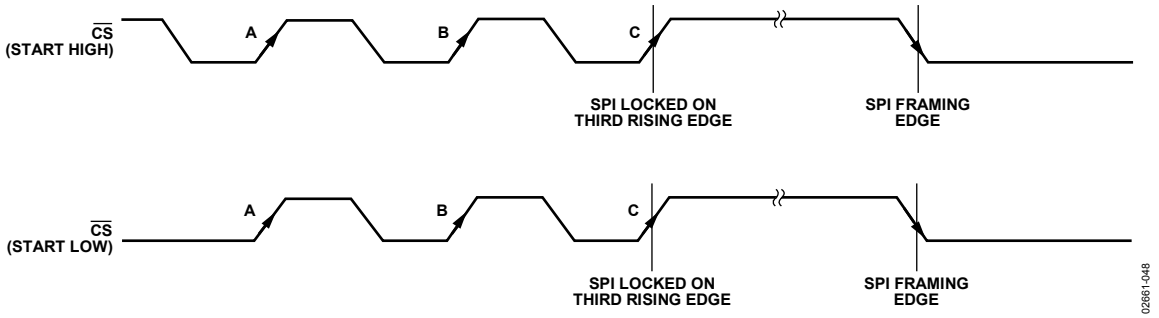

Figure 50. Serial Interface—Selecting and Locking SPI Protocol

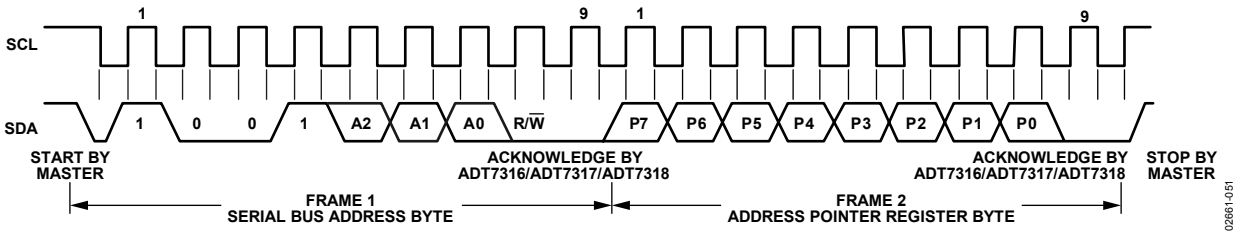

Figure 51. I²C—Writing to the Address Pointer Register to Select a Register for a Subsequent Read Operation

SERIAL INTERFACE

There are two serial interfaces that can be used on this part, the I²C and the SPI interface. The device powers up with the serial interface in I²C mode, but it is not locked into this mode. To stay in I²C mode, it is recommended that the user ties the $\overline{CS}$ line to either V_{CC} or GND. It is not possible to lock the I²C mode, but it is possible to select and lock the SPI mode.

To select and lock the interface into the SPI mode, a number of pulses must be sent down the $\overline{CS}$ (Pin 4) line. The following section describes how this is done.

Once the SPI communication protocol has been locked in, it cannot be unlocked while the device is still powered up. Bit D0 of the SPI Lock Status register (Address 0x7F) is set to 1 when a successful SPI interface lock has been accomplished. To reset the serial interface, the user must power down the part and power up again. A software reset does not reset the serial interface.

SERIAL INTERFACE SELECTION

The $\overline{CS}$ line controls the selection between I²C and SPI. Figure 50 shows the selection process necessary to lock the SPI interface mode.

To communicate to the ADT7316/ADT7317/ADT7318 using the SPI protocol, send three pulses down the $\overline{CS}$ line, as shown in Figure 50. On the third rising edge (marked as C in Figure 50), the part selects and locks the SPI interface. The user is limited to communicating to the device using the SPI protocol.

As per most SPI standards, the $\overline{CS}$ line must be low during every SPI communication to the ADT7316/ADT7317/ ADT7318 and high all other times. Typical examples of how to connect the dual interface as I²C or SPI are shown in Figure 48 and Figure 49.

The following sections describe in detail how to use the I²C and SPI protocols associated with the ADT7316/ADT7317/ ADT7318.

I²C SERIAL INTERFACE

Like all I²C-compatible devices, the ADT7316/ADT7317/ ADT7318 have a 7-bit serial address. The 4 MSBs of this address for the ADT7316/ADT7317/ADT7318 are set to 1001. The 3 LSBs are set by Pin 11, ADD. The ADD pin can be configured three ways to give three different address options: low, floating, and high. Setting the ADD pin low gives a serial bus address of 1001 000, leaving it floating gives the address 1001 010, and setting it high gives the address 1001 011. The recommended pull-up resistor value is 10 kΩ.

There is a programmable SMBus timeout. When this is enabled the SMBus times out after 25 ms of no activity. To enable it, set Bit 6 of the Control Configuration 2 register (Address 0x19). The power-up default is with the SMBus timeout disabled.

The ADT7316/ADT7317/ADT7318 support SMBus packet error checking (PEC) and its use is optional. It is triggered by supplying the extra clocks for the PEC byte. The PEC byte is calculated using CRC-8. The frame clock sequence (FCS) conforms to CRC-8 by the polynomial:

$$C(x) = x^8 + x^2 + x^1 + 1$$

Consult SMBus for more information.

The serial bus protocol operates as follows:

1. The master initiates data transfer by establishing a start condition, defined as a high-to-low transition on the serial data line SDA while the serial clock line SCL remains high. This indicates that an address/data stream follow. All slave peripherals connected to the serial bus respond to the start condition and shift in the next 8 bits, consisting of a 7-bit address (MSB first) plus an R/$\overline{W}$ bit, which determines the direction of the data transfer, that is, whether data is to be written to or read from the slave device. The peripheral whose address corresponds to the transmitted address responds by pulling the data line low during the low period before the ninth clock pulse, known as the acknowledge bit. All other devices on the bus now remain idle, while the selected device waits for data to be read from or written to it. If the R/$\overline{W}$ bit is 0, the master writes to the slave device. If the R/$\overline{W}$ bit is 1, the master reads from the slave device.
2. Data is sent over the serial bus in sequences of nine clock pulses, 8 bits of data followed by an acknowledge bit from the receiver of data. Transitions on the data line must occur during the low period of the clock signal and remain stable during the high period, because a low-to-high transition when the clock is high may be interpreted as a stop signal.
3. When all data bytes have been read or written, stop conditions are established. In write mode, the master pulls the data line high during the 10th clock pulse to assert a stop condition. In read mode, the master device pulls the data line high during the low period before the ninth clock pulse. This is known as no acknowledge. The master takes the data line low during the low period before the 10th clock pulse, then high during the 10th clock pulse to assert a stop condition.

Any number of bytes of data may be transferred over the serial bus in one operation. However, reads and writes cannot be mixed in one operation because the type of operation is determined at the beginning and cannot subsequently be changed without starting a new operation.

The I²C address set up by the ADD pin is not latched by the device until after this address has been sent twice. On the eighth SCL cycle of the second valid communication, the serial bus address is latched in. This is the SCL cycle directly after the device has seen its own I²C serial bus address. Any subsequent changes on this pin have no effect on the I²C serial bus address.

Writing to the ADT7316/ADT7317/ADT7318

Depending on the register being written to, there are two different writes for the ADT7316/ADT7317/ADT7318. It is not possible to do a block write to this part, that is, no I^2C auto-increment.

Writing to the Address Pointer Register for a Subsequent Read

To read data from a particular register, the address pointer register must contain the address of that register. If it does not, the correct address must be written to the address pointer register by performing a single-byte write operation, as shown in Figure 51. The write operation consists of the serial bus address followed by the address pointer byte. No data is written to any of the data registers. A read operation is then performed to read the register.

Writing Data to a Register

All registers are 8-bit registers so only one byte of data can be written to each register. Writing a single byte of data to one of these read/write registers consists of the serial bus address, the data register address written to the address pointer register, followed by the data byte written to the selected data register. This is illustrated in Figure 52. To write to a different register, another start or repeated start is required. If more than one byte of data is sent in one communication operation, the addressed register is repeatedly loaded until the last data byte is sent.

Reading Data from the ADT7316/ADT7317/ADT7318

Reading data from the ADT7316/ADT7317/ADT7318 is done in a 1-byte operation. Reading back the contents of a register is shown in Figure 56. The register address previously had been set up by a single byte write operation to the address pointer register. To read from another register, write to the address pointer register again to set up the relevant register address. Therefore, block reads are not possible, that is, no I^2C auto-increment.

SPI SERIAL INTERFACE

The SPI serial interface of the ADT7316/ADT7317/ADT7318 consists of four wires, $\overline{CS}$, SCLK, DIN, and DOUT. The $\overline{CS}$ is used to select the device when more than one device is connected to the serial clock and data lines. The $\overline{CS}$ is also used to distinguish between any two separate serial communications (see Figure 58). The SCLK is used to clock data in and out of the part. The DIN line is used to write to the registers and the DOUT line is used to read data back from the registers. The recommended pull-up resistor value is between 500 Ω to 820 Ω. Strong pull ups are needed when serial clock speeds (which are close to the maximum limit) are used or when the SPI interface lines are experiencing large capacitive loading. Larger resistor values can be used for pull-up resistors when the serial clock speed is reduced.

The part operates in slave mode and requires an externally applied serial clock to the SCLK input. The serial interface is designed to allow the part to be interfaced to systems that provide a serial clock that is synchronized to the serial data.

There are two types of serial operations, a read and a write. Command words are used to distinguish between a read and a write operation, as shown in Table 58. Address auto-increment is possible in SPI mode.

Table 58. SPI Command Words

Write	Read
0x90 (1001 0000)	0x91 (1001 0001)

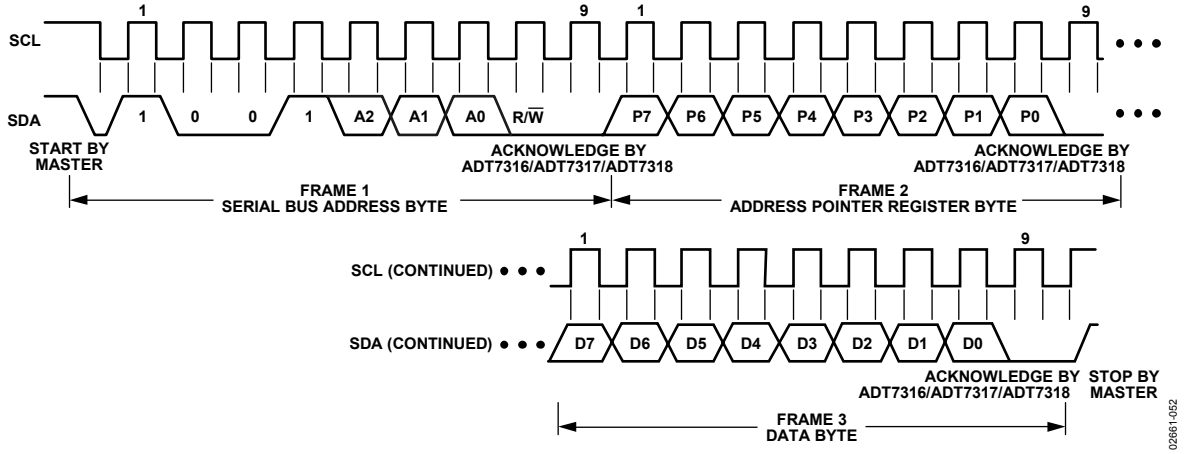

Figure 52. I^2C—Writing to the Address Pointer Register Followed by a Single Byte of Data to the Selected Register

Write Operation

Figure 54 and Figure 55 show the timing diagrams for a write operation to the ADT7316/ADT7317/ADT7318. Data is clocked into the registers on the rising edge of SCLK. When the $\overline{CS}$ line is high, the DIN and DOUT lines are in three-state mode. Only when the $\overline{CS}$ goes from a high to a low does the part accept any data on the DIN line. In SPI mode, the address pointer register is capable of an auto-increment to the next register in the register map without having to load the address pointer register each time. In Figure 54, the register address section provides the first register address that is written to. Subsequent data bytes are written into sequential writable registers. Therefore, after each data byte has been written into a register, the address pointer register auto-increments its value to the next available register. The address pointer register auto-increments from Address 0x00 to Address 0x3F and loops back to start all over again at Address 0x00 when it reaches Address 0x3F.

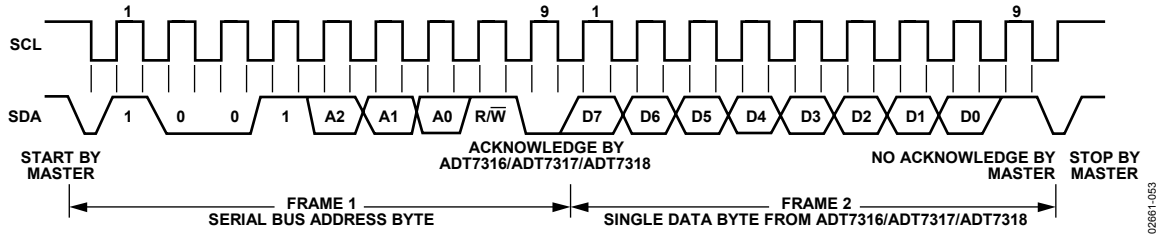

Figure 53. I²C — Reading a Single Byte of Data From a Selected Register

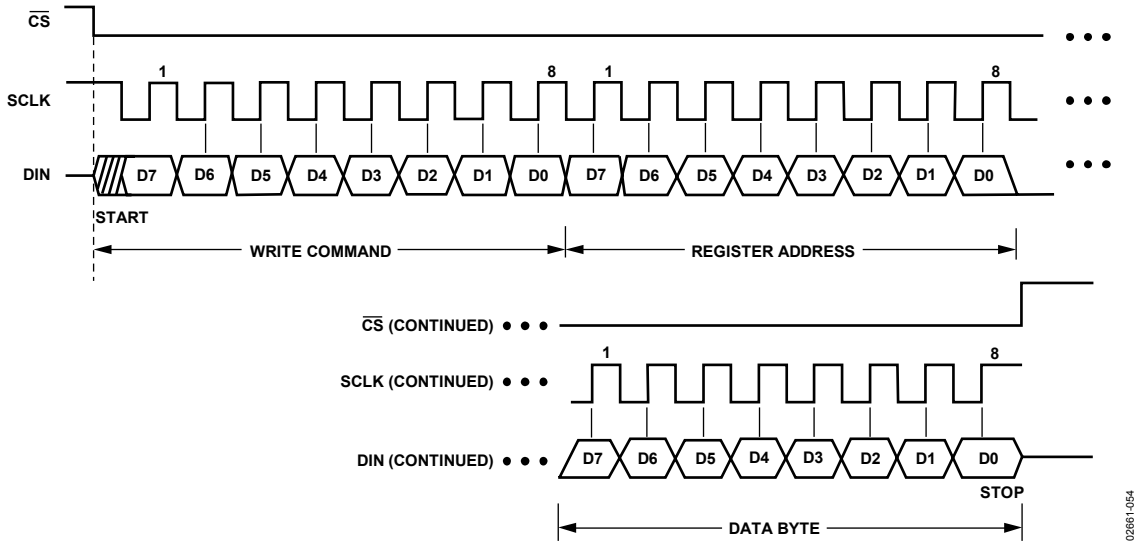

Figure 54. SPI—Writing to the Address Pointer Register Followed by a Single Byte of Data to the Selected Register

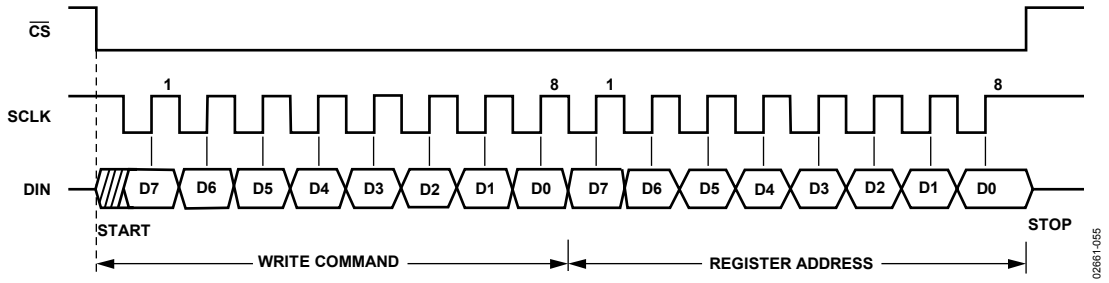

Figure 55. SPI—Writing to the Address Pointer Register to Select a Register for a Subsequent Read Operation

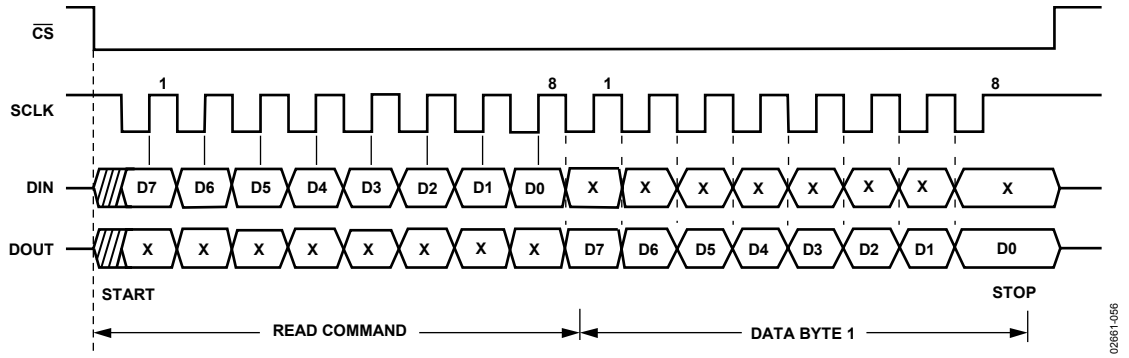

Figure 56. SPI —Reading a Single Byte of Data From a Selected Register

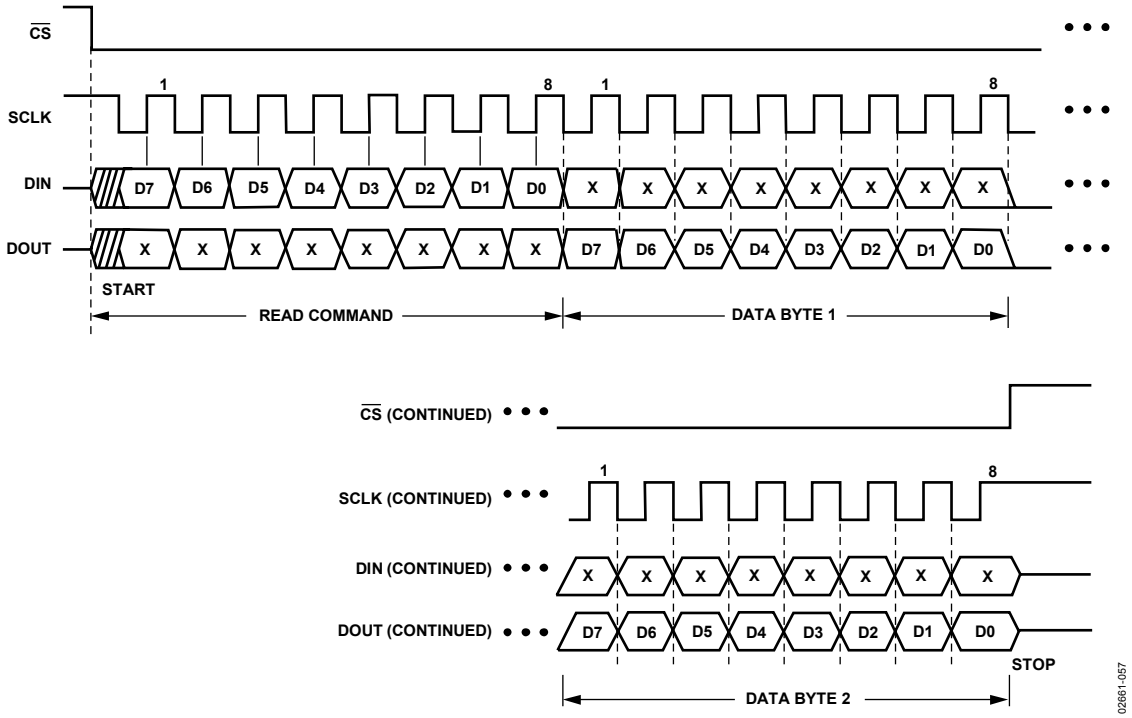

Figure 57. SPI—Reading Two Bytes of Data From Two Sequential Registers

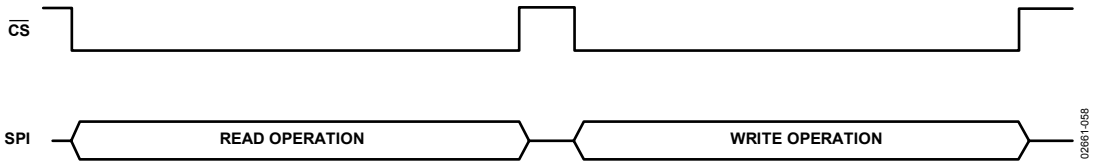

Figure 58. SPI—Correct Use of $\overline{CS}$ During SPI Communication

Read Operation

Figure 56 and Figure 57 show the timing diagrams necessary to accomplish correct read operations. To read back from a register, first write to the address pointer register with the address of the register to read from, as shown in Figure 53. Figure 56 shows the procedure for reading back a single byte of data. The read command is first sent to the part during the first eight clock cycles. As the read command is being sent, irrelevant data is output onto the DOUT line. During the following eight clock cycles, the data contained in the register selected by the address pointer register is output onto the DOUT line. Data is output onto the DOUT line on the falling edge of SCLK. Figure 57 shows the procedure when reading data from two sequential registers. Multiple data reads are possible in SPI interface mode as the address pointer register is auto-incremental. The address pointer register auto-increments from Address 0x00 to Address 0x3F and loops back to start all over again at Address 0x00 when it reaches Address 0x3F.

SMBUS/SPI INT/$\overline{INT}$

The ADT7316/ADT7317/ADT7318 INT/$\overline{INT}$ output is an interrupt line that signals an over-limit/under-limit event on any of the measurement channels if the interrupt on that event has not been disabled. The ADT7316/ADT7317/ADT7318 are slave-only devices and use the SMBus/SPI INT/$\overline{INT}$ as their only means to signal other devices that an event has occurred.

The INT/$\overline{INT}$ pin has an open-drain configuration that allows the outputs of several devices to be wire-AND'ed together when the INT/$\overline{INT}$ pin is active low. Use C6 of the Control Configuration 1 register (Address 0x18) to set the active polarity of the INT/$\overline{INT}$ output. The power-up default is active low. The INT/$\overline{INT}$ output can be disabled or enabled by setting C5 of the Control Configuration 1 register (Address 0x18) to 1 or 0, respectively.

The INT/$\overline{INT}$ output becomes active when either the internal temperature value, the external temperature value, or the V_{DD} value exceeds the values in their corresponding T_{HIGH}/V_{HIGH} or T_{LOW}/V_{LOW} registers. The INT/$\overline{INT}$ output goes inactive again when a conversion result indicates that all measurement channels are within their trip limits, and when the status register associated with the out-of-limit event is read. The two interrupt status registers show which event caused the INT/$\overline{INT}$ pin to go active.

The INT/$\overline{INT}$ output requires an external pull-up resistor. This can be connected to a voltage different from V_{DD} provided that the maximum voltage rating of the INT/$\overline{INT}$ output pin is not exceeded. The value of the pull-up resistor depends on the application but should be large enough to avoid excessive sink currents at the INT/$\overline{INT}$ output, which can heat the chip and affect the temperature reading.

SMBUS Alert Response

The INT/$\overline{INT}$ pin behaves the same way as a SMBus alert pin when the SMBus/I^2C interface is selected. It is an open-drain output and requires a pull-up to V_{DD}. Several INT/$\overline{INT}$ outputs can be wire-AND'ed together so that the common line goes low if one or more of the INT/$\overline{INT}$ outputs goes low. The polarity of the INT/$\overline{INT}$ pin must be set for active low for a number of outputs to be wire-AND'ed together. The INT/$\overline{INT}$ output can operate as a $\overline{SMBALERT}$ function. Slave devices on the SMBus typically cannot signal to the master that they want to talk, but the $\overline{SMBALERT}$ function allows them to do so. $\overline{SMBALERT}$ is used in conjunction with the SMBus general call address.

One or more INT/$\overline{INT}$ outputs can be connected to a common $\overline{SMBALERT}$ line connected to the master. When a $\overline{SMBALERT}$ line is pulled low by one of the devices, the following procedure occurs (see Figure 59).

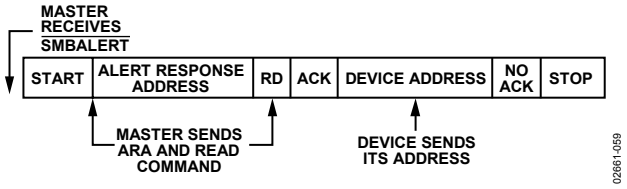

Figure 59. INT/$\overline{INT}$ Responds to $\overline{SMBALERT}$ ARA

1. $\overline{SMBALERT}$ is pulled low.
2. The master initiates a read operation and sends the alert response address (ARA = 0001 100). This is a general call address that must not be used as a specific device address.
3. The devices whose INT/$\overline{INT}$ output is low respond to the alert response address and the master reads its device address. Because the device address is 7 bits long, an LSB of 1 is added. The address of the device is now known and it can be interrogated in the usual way.
4. If more than one devices INT/$\overline{INT}$ output is low, the one with the lowest device address has priority, in accordance with typical SMBus specifications.
5. Once the ADT7316/ADT7317/ADT7318 has responded to the alert response address, it resets its INT/$\overline{INT}$ output, provided that the condition that caused the out-of-limit event no longer exists and the status register associated with the out-of-limit event is read. If the $\overline{SMBALERT}$ line remains low, the master sends the ARA again. It continues to do this until all devices whose $\overline{SMBALERT}$ outputs were low have responded.

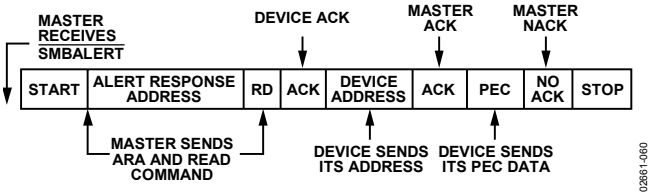

Figure 60. INT/$\overline{INT}$ Responds to $\overline{SMBALERT}$ ARA with Packet Error Checking (PEC)

LAYOUT CONSIDERATIONS

Digital boards can be electrically noisy environments, and care must be taken to protect the analog inputs from noise, particularly when measuring the very small voltages from a remote diode sensor. Take the following precautions:

- Place the ADT7316/ADT7317/ADT7318 as close as possible to the remote sensing diode. Provided that the worst noise sources, such as clock generators, data/address buses, and CRTs are avoided, this distance can be 4 inches to 8 inches.
- Route the D+ and D− tracks close together, in parallel, with grounded guard tracks on each side. Provide a ground plane under the tracks if possible.
- Use wide tracks to minimize inductance and reduce noise pickup. A 10 mil track minimum width and spacing is recommended.

Figure 61. Arrangement of Signal Tracks

- Try to minimize the number of copper/solder joints, which can cause thermocouple effects. Where copper/ solder joints are used, make sure that they are in both the D+ and D− paths and at the same temperature. Thermocouple effects should not be a major problem as 1°C corresponds to about 240 μV, and thermocouple voltages are about 3 μV/°C of the temperature difference. Unless there are two thermocouples with a big temperature differential between them, thermocouple voltages should be much less than 200 mV.
- Place 0.1 μF bypass and 2200 pF input filter capacitors close to the ADT7316/ADT7317/ADT7318.
- If the distance to the remote sensor is more than 8 inches, the use of the twisted pair cable is recommended. This works for distances from 6 feet to 12 feet.
- For really long distances (up to 100 feet), use shielded twisted pair, such as Belden #8451 microphone cable. Connect the twisted pair to D+ and D− and the shield to GND close to the ADT7316/ADT7317/ADT7318. Leave the remote end of the shield unconnected to avoid ground loops.
- Because the measurement technique uses switched current sources, excessive cable and/or filter capacitance can affect the measurement. When using long cables, the filter capacitor may be reduced or removed.

  Cable resistance can also introduce errors. Series resistance of 1 Ω introduces about 0.5°C error.

OUTLINE DIMENSIONS

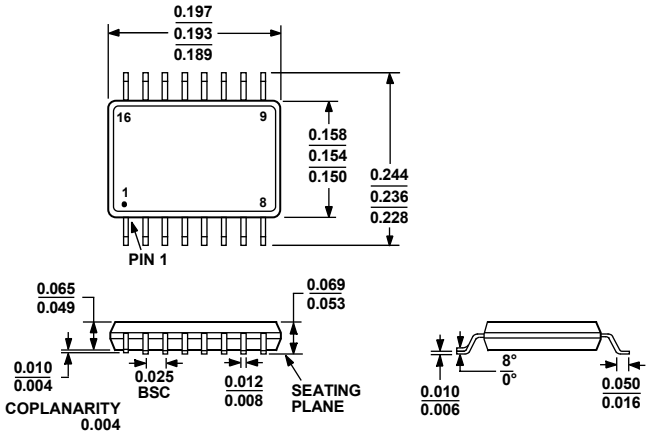

Figure 62. 16-Lead Shrink Small Outline Package [QSOP]
(RQ-16)
Dimensions shown in inches

ORDERING GUIDE

Model	Temperature Range	DAC Resolution	Package Description	Package Option	Ordering Quantity
ADT7318ARQ	−40°C to +120°C	8-Bits	16-Lead QSOP	RQ-16	98
ADT7318ARQ-REEL	−40°C to +120°C	8-Bits	16-Lead QSOP	RQ-16	2,500
ADT7318ARQ-REEL7	−40°C to +120°C	8-Bits	16-Lead QSOP	RQ-16	1,000
ADT7318ARQZ[1]	−40°C to +120°C	8-Bits	16-Lead QSOP	RQ-16	98
ADT7318ARQZ-REEL[1]	−40°C to +120°C	8-Bits	16-Lead QSOP	RQ-16	2,500
ADT7318ARQZ-REEL7[1]	−40°C to +120°C	8-Bits	16-Lead QSOP	RQ-16	1,000
ADT7317ARQ	−40°C to +120°C	10-Bits	16-Lead QSOP	RQ-16	98
ADT7317ARQ-REEL	−40°C to +120°C	10-Bits	16-Lead QSOP	RQ-16	2,500
ADT7317ARQ-REEL7	−40°C to +120°C	10-Bits	16-Lead QSOP	RQ-16	1,000
ADT7317ARQZ[1]	−40°C to +120°C	10-Bits	16-Lead QSOP	RQ-16	98
ADT7317ARQZ-REEL[1]	−40°C to +120°C	10-Bits	16-Lead QSOP	RQ-16	2,500
ADT7317ARQZ-REEL7[1]	−40°C to +120°C	10-Bits	16-Lead QSOP	RQ-16	1,000
ADT7316ARQ	−40°C to +120°C	12-Bits	16-Lead QSOP	RQ-16	98
ADT7316ARQ-REEL	−40°C to +120°C	12-Bits	16-Lead QSOP	RQ-16	1,000
ADT7316ARQ-REEL7	−40°C to +120°C	12-Bits	16-Lead QSOP	RQ-16	1,000
ADT7316ARQZ[1]	−40°C to +120°C	12-Bits	16-Lead QSOP	RQ-16	98
ADT7316ARQZ-REEL[1]	−40°C to +120°C	12-Bits	16-Lead QSOP	RQ-16	2,500
ADT7316ARQZ-REEL7[1]	−40°C to +120°C	12-Bits	16-Lead QSOP	RQ-16	1,000
EVAL-ADT7316EB			Evaluation Board		

[1] Z = Pb-free part.

NOTES

NOTES

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C02661-0-1/07(B)